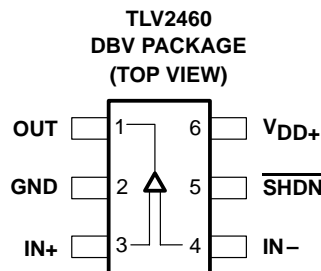


# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

- Rail-to-Rail Output Swing
- Gain Bandwidth Product . . . 6.4 MHz
- $\pm 80$  mA Output Drive Capability
- Supply Current . . . 500  $\mu$ A/channel
- Input Offset Voltage . . . 100  $\mu$ V
- Input Noise Voltage . . . 11 nV/ $\sqrt{\text{Hz}}$
- Slew Rate . . . 1.6 V/ $\mu$ s
- Micropower Shutdown Mode (TLV2460/3/5) . . . 0.3  $\mu$ A/Channel
- Universal Operational Amplifier EVM
- Available in Q-Temp Automotive HighRel Automotive Applications Configuration Control/Print Support Qualification to Automotive Standards



## description

The TLV246x is a family of low-power rail-to-rail input/output operational amplifiers specifically designed for portable applications. The input common-mode voltage range extends beyond the supply rails for maximum dynamic range in low-voltage systems. The amplifier output has rail-to-rail performance with high-output-drive capability, solving one of the limitations of older rail-to-rail input/output operational amplifiers. This rail-to-rail dynamic range and high output drive make the TLV246x ideal for buffering analog-to-digital converters.

The operational amplifier has 6.4 MHz of bandwidth and 1.6 V/ $\mu$ s of slew rate with only 500  $\mu$ A of supply current, providing good ac performance with low power consumption. Three members of the family offer a shutdown terminal, which places the amplifier in an ultralow supply current mode ( $I_{DD} = 0.3 \mu\text{A/ch}$ ). While in shutdown, the operational-amplifier output is placed in a high-impedance state. DC applications are also well served with an input noise voltage of 11 nV/ $\sqrt{\text{Hz}}$  and input offset voltage of 100  $\mu$ V.

This family is available in the low-profile SOT23, MSOP, and TSSOP packages. The TLV2460 is the first rail-to-rail input/output operational amplifier with shutdown available in the 6-pin SOT23, making it perfect for high-density circuits. The family is specified over an expanded temperature range ( $T_A = -40^\circ\text{C}$  to  $125^\circ\text{C}$ ) for use in industrial control and automotive systems, and over the military temperature range ( $T_A = -55^\circ\text{C}$  to  $125^\circ\text{C}$ ) for use in military systems.

## SELECTION GUIDE

DEVICE	V <sub>DD</sub> [V]	V <sub>IO</sub> [ $\mu$ V]	I <sub>DD</sub> /ch [ $\mu$ A]	I <sub>IB</sub> [pA]	GBW [MHz]	SLEW RATE [V/ $\mu$ s]	V <sub>n</sub> , 1 kHz [nV/ $\sqrt{\text{Hz}}$ ]	I <sub>O</sub> [mA]	SHUTDOWN	RAIL-RAIL
TLV246x(A)	2.7–6	150	550	1300	6.4	1.6	11	25	Y	I/O
TLV277x(A)	2.5–5.5	360	1000	2	5.1	10.5	17	6	Y	O
TLV247x(A)	2.7–6	250	600	2.5	2.8	1.5	15	20	Y	I/O
TLV245x(A)	2.7–6	20	23	500	0.22	0.11	52	10	Y	I/O
TLV225x(A)	2.7–8	200	35	1	0.2	0.12	19	3	—	—
TLV226x(A)	2.7–8	300	200	1	0.71	0.55	12	3	—	—



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA

## FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT

### OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

#### TLV2460C//AI and TLV2461C//AI AVAILABLE OPTIONS

T <sub>A</sub>	V <sub>IOmax</sub> AT 25°C	PACKAGED DEVICES			
		SMALL OUTLINE (D)	SOT-23† (DBV)	SYMBOL	PLASTIC DIP (P)
0°C to 70°C	2000 µV	TLV2460CD TLV2461CD	TLV2460CDBV TLV2461CDBV	VAOC VAPC	TLV2460CP TLV2461CP
–40°C to 125°C	2000 µV	TLV2460ID TLV2461ID	TLV2460IDBV TLV2461IDBV	VAOI VAPI	TLV2460IP TLV2461IP
	1500 µV	TLV2460AID TLV2461AID	— —	— —	TLV2460AIP TLV2461AIP

† This package is available taped and reeled. To order this packaging option, add an R suffix to the part number (e.g., TLV2460CDR).

‡ Chip forms are tested at T<sub>A</sub> = 25°C only.

#### TLV2460M/AM/Q/AQ and TLV2461M/AM/Q/AQ AVAILABLE OPTIONS

T <sub>A</sub>	V <sub>IOmax</sub> AT 25°C	PACKAGED DEVICES				
		SMALL OUTLINE† (D)	SMALL OUTLINE† (PW)	CERAMIC DIP (JG)	CERAMIC FLATPACK (U)	CHIP CARRIER (FK)
–40°C to 125°C	2000 µV	TLV2460QD TLV2461QD	TLV2460QPW TLV2461QPW	— —	— —	— —
	1500 µV	TLV2460AQD TLV2461AQD	TLV2460AQPW TLV2461AQPW	— —	— —	— —
–55°C to 125°C	2000 µV	— —	— —	TLV2460MJG TLV2461MJG	TLV2460MU TLV2461MU	TLV2460MFK TLV2461MFK
	1500 µV	— —	— —	TLV2460AMJG TLV2461AMJG	TLV2460AMU TLV2461AMU	TLV2460AMFK TLV2461AMFK

† This package is available taped and reeled. To order this packaging option, add an R suffix to the part number (e.g., TLV2460QDR).

#### TLV2462C//AI and TLV2463C//AI AVAILABLE OPTIONS

T <sub>A</sub>	V <sub>IOmax</sub> AT 25°C	PACKAGED DEVICES						
		SMALL OUTLINE† (D)	MSOP (DGK)	SYMBOL	MSOP† (DGS)	SYMBOL	PLASTIC DIP (N)	PLASTIC DIP (P)
0°C to 70°C	2000 µV	TLV2462CD TLV2463CD	TLV2462CDGK —	xxTIAAI	— TLV2463CDGS	— xxTIAAK	— TLV2463CN	TLV2462CP —
–40°C to 125°C	2000 µV	TLV2462ID TLV2463ID	TLV2462IDGK —	xxTIAAJ	— TLV2463IDGS	— xxTIAAL	— TLV2463IN	TLV2462IP —
	1500 µV	TLV2462AID TLV2463AID	— —	— —	— —	— —	— TLV2463AIN	TLV2462AIP —

† This package is available taped and reeled. To order this packaging option, add an R suffix to the part number (e.g., TLV2462CDR).

‡ Chip forms are tested at T<sub>A</sub> = 25°C only.



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**TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA**  
**FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT**  
**OPERATIONAL AMPLIFIERS WITH SHUTDOWN**

SLOS220I – JULY 1998 – REVISED MARCH 2001

**TLV2462M/AM/Q/AQ and TLV2463M/AM/Q/AQ AVAILABLE OPTIONS**

$T_A$	$V_{IOmax}$ AT 25°C	PACKAGED DEVICES					
		SMALL OUTLINE† (D)	SMALL OUTLINE† (PW)	CERAMIC DIP (JG)	CERAMIC DIP (J)	CERAMIC FLATPACK (U)	CHIP CAR- RIER (FK)
–40°C to 125°C	2000 $\mu$ V	TLV2462QD TLV2463QD	TLV2462QPW TLV2463QPW	— —	— —	— —	— —
	1500 $\mu$ V	TLV2462AQD TLV2463AQD	TLV2462AQPW TLV2463AQPW	— —	— —	— —	— —
–55°C to 125°C	2000 $\mu$ V	— —	— —	TLV2462MJG —	— TLV2463MJ	TLV2462MU	TLV2462MFK TLV2463MFK
	1500 $\mu$ V	— —	— —	TLV2462AMJG —	— TLV2463AMJ	TLV2462AMU	TLV2462AMFK TLV2463AMFK

† This package is available taped and reeled. To order this packaging option, add an R suffix to the part number (e.g., TLV2462QDR).

**TLV2464C/I/AI and TLV2465C/I/AI AVAILABLE OPTIONS**

$T_A$	$V_{IOmax}$ AT 25°C	PACKAGED DEVICES		
		SMALL OUTLINE (D)	PLASTIC DIP (N)	TSSOP (PW)
0°C to 70°C	2000 $\mu$ V	TLV2464CD TLV2465CD	TLV2464CN TLV2465CN	TLV2464CPW TLV2465CPW
–40°C to 125°C	2000 $\mu$ V	TLV2464ID TLV2465ID	TLV2464IN TLV2465IN	TLV2464IPW TLV2465IPW
	1500 $\mu$ V	TLV2464AID TLV2465AID	TLV2464AIN TLV2465AIN	TLV2464AIPW TLV2465AIPW

† This package is available taped and reeled. To order this packaging option, add an R suffix to the part number (e.g., TLV2464CDR).

‡ Chip forms are tested at  $T_A = 25^\circ\text{C}$  only.

**TLV2464M/AM/Q/AQ and TLV2465M/AM/Q/AQ AVAILABLE OPTIONS**

$T_A$	$V_{IOmax}$ AT 25°C	PACKAGED DEVICES			
		SMALL OUTLINE† (D)	SMALL OUTLINE† (PW)	CERAMIC DIP (J)	CHIP CARRIER (FK)
–40°C to 125°C	2000 $\mu$ V	TLV2464QD TLV2465QD	TLV2464QPW TLV2465QPW	— —	— —
	1500 $\mu$ V	TLV2464AQD TLV2465AQD	TLV2464AQPW TLV2465AQPW	— —	— —
–55°C to 125°C	2000 $\mu$ V	— —	— —	TLV2464MJ TLV2465MJ	TLV2464MFK TLV2465MFK
	1500 $\mu$ V	— —	— —	TLV2464AMJ TLV2465AMJ	TLV2464AMFK TLV2465AMFK

† This package is available taped and reeled. To order this packaging option, add an R suffix to the part number (e.g., TLV2464QDR).



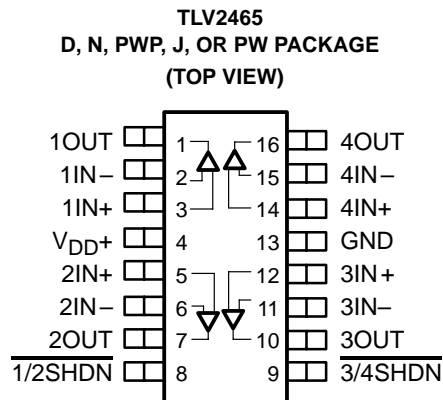
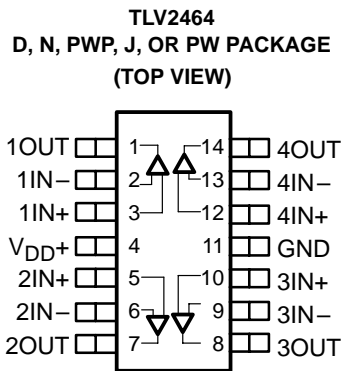
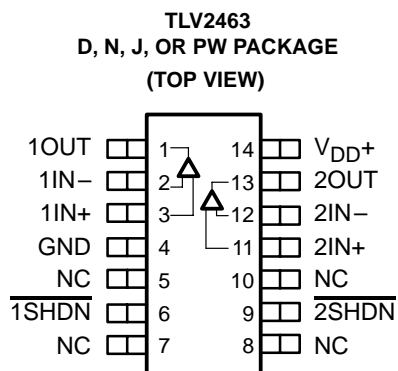
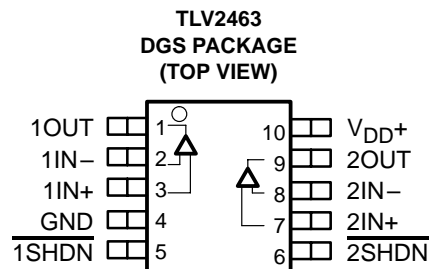
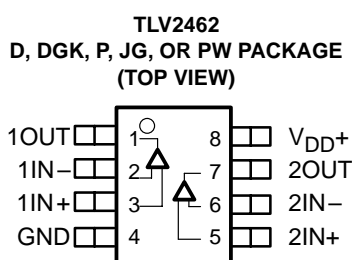
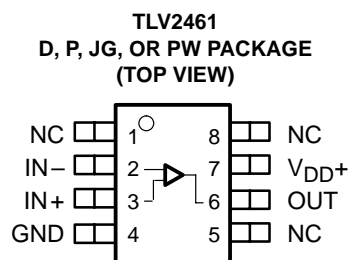
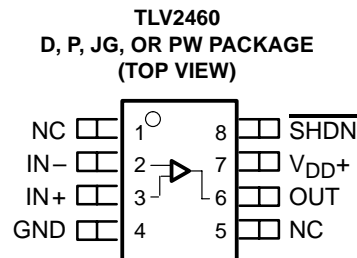
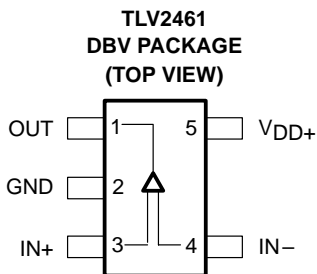
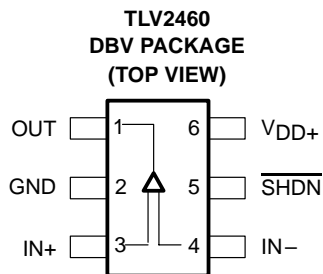
# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA

## FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT

### OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

#### TLV246x PACKAGE PINOUTS



NC – No internal connection

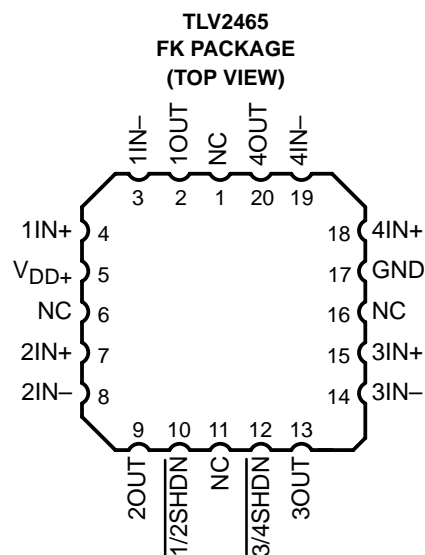
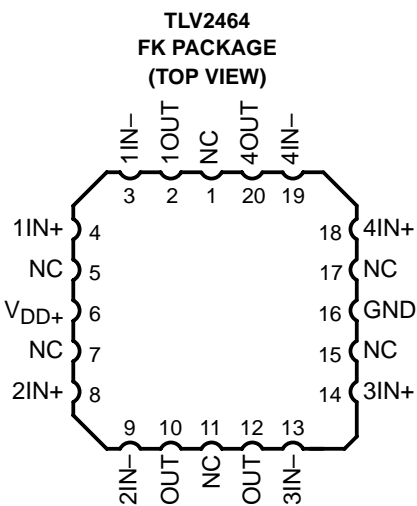
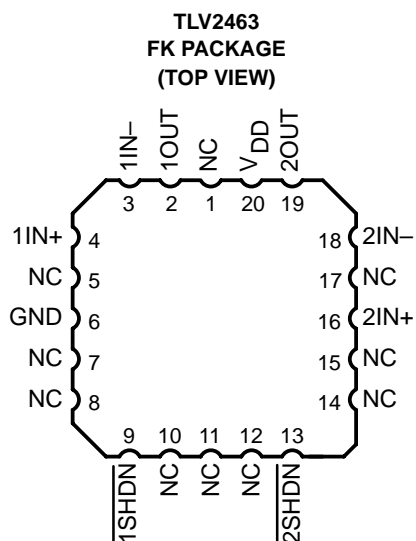
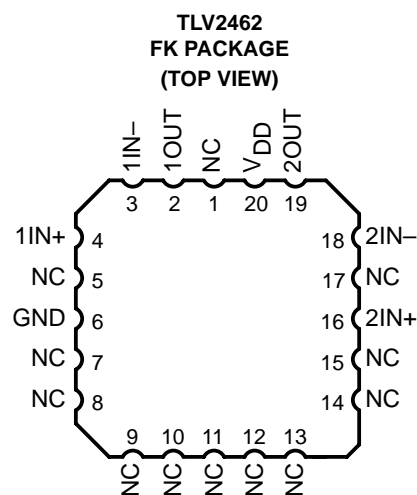
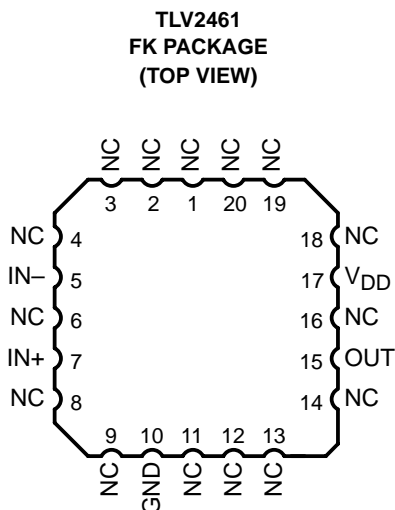
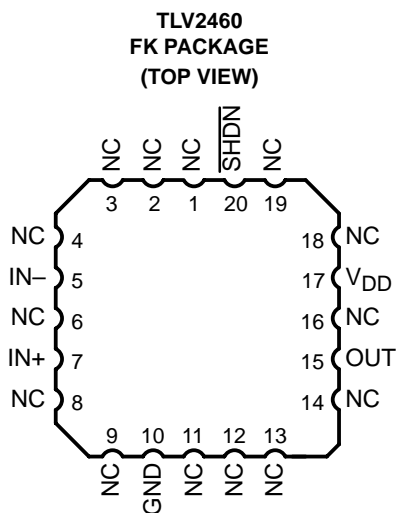
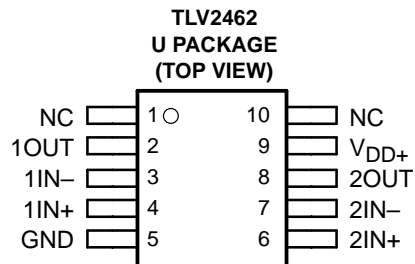
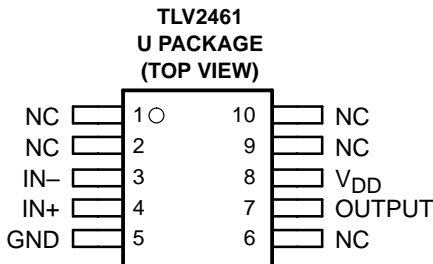
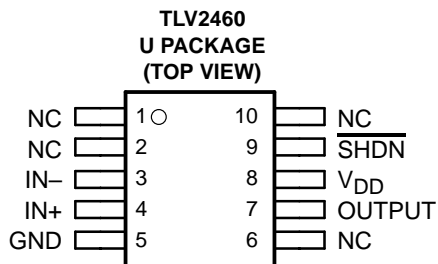
# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA

## FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT

### OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

#### TLV246x PACKAGE PINOUTS (continued)



NC – No internal connection



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# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA

## FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, $V_{DD}$ (see Note 1)	6 V
Differential input voltage, $V_{ID}$	– 0.2 V to $V_{DD} + 0.2$ V
Input current, $I_I$ (any input)	$\pm 200$ mA
Output current, $I_O$	$\pm 175$ mA
Total input current, $I_I$ (into $V_{DD+}$ )	175 mA
Total output current, $I_O$ (out of GND)	175 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, $T_A$ : C suffix	0°C to 70°C
I and Q suffix	–40°C to 125°C
M suffix	–55°C to 125°C
Maximum junction temperature, $T_J$	150°C
Storage temperature range, $T_{stg}$	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values, except differential voltages, are with respect to GND.

DISSIPATION RATING TABLE FOR C and I SUFFIX

PACKAGE	$\theta_{JC}$ (°C/W)	$\theta_{JA}$ (°C/W)	$T_A \leq 25^\circ\text{C}$ POWER RATING	$T_A < 125^\circ\text{C}$ POWER RATING
D (8)	38.3	176	710 mW	142 mW
D (14)	26.9	122.6	1022 mW	204.4 mW
D (16)	25.7	114.7	1090 mW	218 mW
DBV (5)	55	324.1	385 mW	77.1 mW
DBV (6)	55	294.3	425 mW	84.9 mW
DGK	54.2	259.9	481 mW	96.2 mW
DGS	54.1	257.7	485 mW	97 mW
N (14, 16)	32	78	1600 mW	320.5 mW
P (8)	41	104	1200 mW	240.4 mW
PW (14)	29.3	173.6	720 mW	144 mW
PW (16)	28.7	161.4	774 mW	154.9 mW

NOTE: Thermal resistances are not production tested and are for informational purposes only.

DISSIPATION RATING TABLE FOR Q and M SUFFIX

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}$ <sup>‡</sup>	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 85^\circ\text{C}$ POWER RATING	$T_A = 125^\circ\text{C}$ POWER RATING
FK	1375 mW	11.0 mW/°C	880 mW	715 mW	275 mW
JG	1050 mW	8.4 mW/°C	672 mW	546 mW	210 mW
U	675 mW	5.4 mW/°C	432 mW	350 mW	135 mW

<sup>‡</sup> This is the inverse of the traditional junction-to-ambient thermal resistance ( $R\theta_{JA}$ ). Thermal resistances are not production tested and are for informational purposes only.



**TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA**  
**FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT**  
**OPERATIONAL AMPLIFIERS WITH SHUTDOWN**

SLOS220I – JULY 1998 – REVISED MARCH 2001

**recommended operating conditions**

		MIN	MAX	UNIT
Supply voltage, $V_{DD}$	Single supply	2.7	6	V
	Split supply	$\pm 1.35$	$\pm 3$	
Common-mode input voltage range, $V_{ICR}$		-0.2	$V_{DD}+0.2$	V
Operating free-air temperature, $T_A$	C-suffix	0	70	$^{\circ}\text{C}$
	I-suffix and Q-suffix	-40	125	
	M-suffix	-55	125	
Shutdown on/off voltage level <sup>‡</sup>	$V_{IH}$	2		V
	$V_{IL}$		0.7	

<sup>‡</sup> Relative to voltage on the GND terminal of the device.

**electrical characteristics at specified free-air temperature,  $V_{DD} = 3\text{ V}$  (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	$T_A$ <sup>†</sup>	MIN	TYP	MAX	UNIT
$V_{IO}$ Input offset voltage	$V_{DD} = 3\text{ V}$ , $V_{IC} = 1.5\text{ V}$ , $V_O = 1.5\text{ V}$ , $R_S = 50\ \Omega$	25 $^{\circ}\text{C}$		100	2000	$\mu\text{V}$
		Full range			2200	
		25 $^{\circ}\text{C}$		150	1500	
		Full range			1700	
$\alpha_{VIO}$ Temperature coefficient of input offset voltage				2		$\mu\text{V}/^{\circ}\text{C}$
$I_{IO}$ Input offset current	$V_{DD} = 3\text{ V}$ , $V_{IC} = 1.5\text{ V}$ , $V_O = 1.5\text{ V}$ , $R_S = 50\ \Omega$	25 $^{\circ}\text{C}$		2.8	7	nA
		Full range			20	
$I_{IB}$ Input bias current	$V_{DD} = 3\text{ V}$ , $V_{IC} = 1.5\text{ V}$ , $V_O = 1.5\text{ V}$ , $R_S = 50\ \Omega$	25 $^{\circ}\text{C}$		4.4	14	nA
		Full range			25	
		Full range			75	
		Full range			75	
$V_{OH}$ High-level output voltage	$I_{OH} = -2.5\text{ mA}$	25 $^{\circ}\text{C}$		2.9		V
		Full range	2.8			
	$I_{OH} = -10\text{ mA}$	25 $^{\circ}\text{C}$		2.7		
		Full range	2.5			
$V_{OL}$ Low-level output voltage	$V_{IC} = 1.5\text{ V}$ , $I_{OL} = 2.5\text{ mA}$	25 $^{\circ}\text{C}$		0.1		V
		Full range			0.2	
	$V_{IC} = 1.5\text{ V}$ , $I_{OL} = 10\text{ mA}$	25 $^{\circ}\text{C}$		0.3		
		Full range			0.5	
$I_{OS}$ Short-circuit output current	Sourcing	25 $^{\circ}\text{C}$		50		mA
		Full range	20			
	Sinking	25 $^{\circ}\text{C}$		40		
		Full range	20			
$I_O$ Output current	Measured 1 V from rail	25 $^{\circ}\text{C}$		$\pm 40$		mA
$A_{VD}$ Large-signal differential voltage amplification	$R_L = 10\text{ k}\Omega$	25 $^{\circ}\text{C}$	90	105		dB
		Full range	89			
$r_{i(d)}$ Differential input resistance		25 $^{\circ}\text{C}$		$10^9$		$\Omega$

<sup>†</sup> Full range is 0 $^{\circ}\text{C}$  to 70 $^{\circ}\text{C}$  for the C suffix, -40 $^{\circ}\text{C}$  to 125 $^{\circ}\text{C}$  for the I and Q suffixes, and -55 $^{\circ}\text{C}$  to 125 $^{\circ}\text{C}$  for the M suffix.



# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA

## FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT

### OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

**electrical characteristics at specified free-air temperature,  $V_{DD} = 3\text{ V}$  (unless otherwise noted)**  
(continued)

PARAMETER	TEST CONDITIONS	$T_A^\dagger$	MIN	TYP	MAX	UNIT
$C_{i(c)}$ Common-mode input capacitance	$f = 10\text{ kHz}$	$25^\circ\text{C}$		7		pF
$z_o$ Closed-loop output impedance	$f = 100\text{ kHz}$ , $A_V = 10$	$25^\circ\text{C}$		33		$\Omega$
CMRR Common-mode rejection ratio	$V_{ICR} = -0.2\text{ V to } 3.2\text{ V}$ , $R_S = 50\ \Omega$	$25^\circ\text{C}$	66	80		dB
		TLV246xC	Full range	64		
		TLV246xI/Q/M	Full range	60		
$k_{SVR}$ Supply voltage rejection ratio ( $\Delta V_{DD} / \Delta V_{IO}$ )	$V_{DD} = 2.7\text{ V to } 6\text{ V}$ , No load	$25^\circ\text{C}$	80	85		dB
		Full range	75			
	$V_{DD} = 3\text{ V to } 5\text{ V}$ , No load	$25^\circ\text{C}$	85	95		
		Full range	80			
$I_{DD}$ Supply current (per channels)	$V_O = 1.5\text{ V}$ , No load	$25^\circ\text{C}$		0.5	0.575	mA
		Full range			0.9	
$I_{DD(SHDN)}$ Supply current in shutdown (TLV2460, TLV2463, TLV2465)	SHDN < 0.7 V, Per channel in shutdown	$25^\circ\text{C}$		0.3		$\mu\text{A}$
		Full range			2.5	

$^\dagger$  Full range is  $0^\circ\text{C}$  to  $70^\circ\text{C}$  for the C suffix,  $-40^\circ\text{C}$  to  $125^\circ\text{C}$  for the I and Q suffixes, and  $-55^\circ\text{C}$  to  $125^\circ\text{C}$  for the M suffix.

**operating characteristics at specified free-air temperature,  $V_{DD} = 3\text{ V}$  (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	$T_A^\dagger$	MIN	TYP	MAX	UNIT
SR Slew rate at unity gain	$V_O(PP) = 2\text{ V}$ , $R_L = 10\text{ k}\Omega$	$25^\circ\text{C}$	1	1.6		V/ $\mu\text{s}$
		Full range	0.8			
$V_n$ Equivalent input noise voltage	$f = 100\text{ Hz}$	$25^\circ\text{C}$		16		nV/ $\sqrt{\text{Hz}}$
	$f = 1\text{ kHz}$	$25^\circ\text{C}$		11		
$I_n$ Equivalent input noise current	$f = 1\text{ kHz}$	$25^\circ\text{C}$		0.13		pA/ $\sqrt{\text{Hz}}$
THD + N Total harmonic distortion plus noise	$V_O(PP) = 2\text{ V}$ , $R_L = 10\text{ k}\Omega$ , $f = 1\text{ kHz}$	$A_V = 1$		0.006%		
		$A_V = 10$		0.02%		
		$A_V = 100$		0.08%		
$t_{(on)}$ Amplifier turnon time	$A_V = 1$ , $R_L = 10\text{ k}\Omega$	Both channels		7.6		$\mu\text{s}$
		Channel 1 only, Channel 2 on		7.65		
$t_{(off)}$ Amplifier turnoff time	$A_V = 1$ , $R_L = 10\text{ k}\Omega$	Both channels		333		ns
		Channel 1 only, Channel 2 on		328		
		Channel 2 only, Channel 1 on		329		
Gain-bandwidth product	$f = 10\text{ kHz}$ , $C_L = 160\text{ pF}$	$R_L = 10\text{ k}\Omega$ , $25^\circ\text{C}$		5.2		MHz
$t_s$ Settling time	$V(\text{STEP})_{PP} = 2\text{ V}$ , $A_V = -1$ , $C_L = 10\text{ pF}$ , $R_L = 10\text{ k}\Omega$	0.1%		1.47		$\mu\text{s}$
		0.01%		1.78		
	$V(\text{STEP})_{PP} = 2\text{ V}$ , $A_V = -1$ , $C_L = 56\text{ pF}$ , $R_L = 10\text{ k}\Omega$	0.1%		1.77		
		0.01%		1.98		
$\phi_m$ Phase margin at unity gain	$R_L = 10\text{ k}\Omega$ , $C_L = 160\text{ pF}$	$25^\circ\text{C}$		44°		
Gain margin		$25^\circ\text{C}$		7		dB

$^\dagger$  Full range is  $0^\circ\text{C}$  to  $70^\circ\text{C}$  for the C suffix,  $-40^\circ\text{C}$  to  $125^\circ\text{C}$  for the I and Q suffixes, and  $-55^\circ\text{C}$  to  $125^\circ\text{C}$  for the M suffix.





**TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA**  
**FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT**  
**OPERATIONAL AMPLIFIERS WITH SHUTDOWN**

SLOS220I – JULY 1998 – REVISED MARCH 2001

**electrical characteristics at specified free-air temperature,  $V_{DD} = 5\text{ V}$  (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	$T_A^\dagger$	MIN	TYP	MAX	UNIT
$V_{IO}$ Input offset voltage	$V_{DD} = 5\text{ V}$ , $V_{IC} = 2.5\text{ V}$ , $V_O = 2.5\text{ V}$ , $R_S = 50\ \Omega$	25°C		150	2000	$\mu\text{V}$
		Full range			2200	
		25°C		150	1500	
		Full range			1700	
$\alpha_{VIO}$ Temperature coefficient of input offset voltage		25°C		2		$\mu\text{V}/^\circ\text{C}$
$I_{IO}$ Input offset current	$V_{DD} = 5\text{ V}$ , $V_{IC} = 2.5\text{ V}$ , $V_O = 2.5\text{ V}$ , $R_S = 50\ \Omega$	25°C		0.3	7	nA
		Full range			15	
		Full range			60	
$I_{IB}$ Input bias current	$V_{DD} = 5\text{ V}$ , $V_{IC} = 2.5\text{ V}$ , $V_O = 2.5\text{ V}$ , $R_S = 50\ \Omega$	25°C		1.3	14	nA
		Full range			30	
		Full range			60	
$V_{OH}$ High-level output voltage	$I_{OH} = -2.5\text{ mA}$	25°C		4.9		V
		Full range		4.8		
	$I_{OH} = -10\text{ mA}$	25°C		4.8		
		Full range		4.7		
$V_{OL}$ Low-level output voltage	$V_{IC} = 2.5\text{ V}$ , $I_{OL} = 2.5\text{ mA}$	25°C		0.1		V
		Full range			0.2	
	$V_{IC} = 2.5\text{ V}$ , $I_{OL} = 10\text{ mA}$	25°C		0.2		
		Full range			0.3	
$I_{OS}$ Short-circuit output current	Sourcing	25°C		145		mA
		Full range		60		
	Sinking	25°C		100		
		Full range		60		
$I_O$ Output current	Measured at 1 V from rail	25°C		$\pm 80$		mA
$A_{VD}$ Large-signal differential voltage amplification	$V_{IC} = 2.5\text{ V}$ , $R_L = 10\text{ k}\Omega$ , $V_O = 1\text{ V to }4\text{ V}$	25°C		92	109	dB
		Full range		90		
$r_i(d)$ Differential input resistance		25°C		$10^9$		$\Omega$
$c_i(c)$ Common-mode input capacitance	$f = 10\text{ kHz}$	25°C		7		pF
$z_o$ Closed-loop output impedance	$f = 100\text{ kHz}$ , $A_V = 10$	25°C		29		$\Omega$
CMRR Common-mode rejection ratio	$V_{ICR} = -0.2\text{ V to }5.2\text{ V}$ , $R_S = 50\ \Omega$	25°C		71	85	dB
		Full range		69		
		Full range		60		
$k_{SVR}$ Supply voltage rejection ratio ( $\Delta V_{DD} / \Delta V_{IO}$ )	$V_{DD} = 2.7\text{ V to }6\text{ V}$ , No load	25°C		80	85	dB
		Full range		75		
	$V_{DD} = 3\text{ V to }5\text{ V}$ , No load	25°C		85	95	dB
		Full range		80		
$I_{DD}$ Supply current (per channel)	$V_O = 2.5\text{ V}$ , No load,	25°C		0.55	0.65	mA
		Full range			1	
$I_{DD(SHDN)}$ Supply current in shutdown (TLV2460, TLV2463, TLV2465)	SHDN < 0.7 V, Per channels in shutdown	25°C		1		$\mu\text{A}$
		Full range			3	

$^\dagger$  Full range is 0°C to 70°C for the C suffix, -40°C to 125°C for the I and Q suffixes, and -55°C to 125°C for the M suffix.



**TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA**  
**FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT**  
**OPERATIONAL AMPLIFIERS WITH SHUTDOWN**

SLOS220I – JULY 1998 – REVISED MARCH 2001

**operating characteristics at specified free-air temperature,  $V_{DD} = 5\text{ V}$  (unless otherwise noted)**

PARAMETER		TEST CONDITIONS		T <sub>A</sub> †	MIN	TYP	MAX	UNIT
SR	Slew rate at unity gain	V <sub>O</sub> (PP) = 2 V, R <sub>L</sub> = 10 kΩ		C <sub>L</sub> = 160 pF,	25°C	1	1.6	V/μs
					Full range	0.8		
V <sub>n</sub>	Equivalent input noise voltage	f = 100 Hz		25°C	14		nV/√Hz	
		f = 1 kHz		25°C	11			
I <sub>n</sub>	Equivalent input noise current	f = 100 Hz		25°C	0.13		pA/√Hz	
THD + N	Total harmonic distortion plus noise	V <sub>O</sub> (PP) = 4 V, R <sub>L</sub> = 10 kΩ, f = 10 kHz	A <sub>V</sub> = 1	25°C	0.004%			
			A <sub>V</sub> = 10		0.01%			
			A <sub>V</sub> = 100		0.04%			
t <sub>(on)</sub>	Amplifier turnon time	A <sub>V</sub> = 1, R <sub>L</sub> = 10 kΩ	Both channels	25°C	7.6		μs	
			Channel 1 only, Channel 2 on		7.65			
			Channel 2 only, Channel 1 on		7.25			
t <sub>(off)</sub>	Amplifier turnoff time	A <sub>V</sub> = 1, R <sub>L</sub> = 10 kΩ	Both channels	25°C	333		ns	
			Channel 1 only, Channel 2 on		328			
			Channel 2 only, Channel 1 on		329			
Gain-bandwidth product		f = 10 kHz, C <sub>L</sub> = 160 pF	R <sub>L</sub> = 10 kΩ,	25°C	6.4		MHz	
t <sub>s</sub>	Settling time	V <sub>(STEP)</sub> PP = 2 V, A <sub>V</sub> = −1, C <sub>L</sub> = 10 pF, R <sub>L</sub> = 10 kΩ	0.1%	25°C	1.53		μs	
			0.01%		1.83			
		V <sub>(STEP)</sub> PP = 2 V, A <sub>V</sub> = −1, C <sub>L</sub> = 56 pF, R <sub>L</sub> = 10 kΩ	0.1%		3.13			
			0.01%		3.33			
φ <sub>m</sub>	Phase margin at unity gain	R <sub>L</sub> = 10 kΩ, C <sub>L</sub> = 160 pF		25°C	45°			
	Gain margin			25°C	7		dB	

$^\dagger$  Full range is 0°C to 70°C for the C suffix, –40°C to 125°C for the I and Q suffixes, and –55°C to 125°C for the M suffix.

**TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA**  
**FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT**  
**OPERATIONAL AMPLIFIERS WITH SHUTDOWN**

SLOS220I – JULY 1998 – REVISED MARCH 2001

**TYPICAL CHARACTERISTICS**

**Table of Graphs**

			<b>FIGURE</b>
$V_{IO}$	Input offset voltage	vs Common-mode input voltage	1, 2
$I_{IB}$	Input bias current	vs Free-air temperature	3, 4
$I_{IO}$	Input offset current	vs Free-air temperature	3, 4
$V_{OH}$	High-level output voltage	vs High-level output current	5, 6
$V_{OL}$	Low-level output voltage	vs Low-level output current	7, 8
$V_{O(PP)}$	Peak-to-peak output voltage	vs Frequency	9, 10
	Open-loop gain	vs Frequency	11, 12
	Phase	vs Frequency	11, 12
$A_{VD}$	Differential voltage amplification	vs Load resistance	13
	Capacitive load	vs Load resistance	14
$Z_o$	Output impedance	vs Frequency	15, 16
CMRR	Common-mode rejection ratio	vs Frequency	17
$k_{SVR}$	Supply-voltage rejection ratio	vs Frequency	18, 19
$I_{DD}$	Supply current	vs Supply voltage	20
		vs Free-air temperature	21
	Amplifier turnon characteristics		22
	Amplifier turnoff characteristics		23
	Supply current turnon		24
	Supply current turnoff		25
	Shutdown supply current	vs Free-air temperature	26
SR	Slew rate	vs Supply voltage	27
$V_n$	Equivalent input noise voltage	vs Frequency	28, 29
		vs Common-mode input voltage	30, 31
THD	Total harmonic distortion	vs Frequency	32, 33
THD+N	Total harmonic distortion plus noise	vs Peak-to-peak signal amplitude	34, 35
$\phi_m$	Phase margin	vs Frequency	11, 12
		vs Load capacitance	36
		vs Free-air temperature	37
	Gain bandwidth product	vs Supply voltage	38
		vs Free-air temperature	39
	Large signal follower		40, 41
	Small signal follower		42, 43
	Inverting large signal		44, 45
	Inverting small signal		46, 47



# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA

## FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT

### OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

#### TYPICAL CHARACTERISTICS

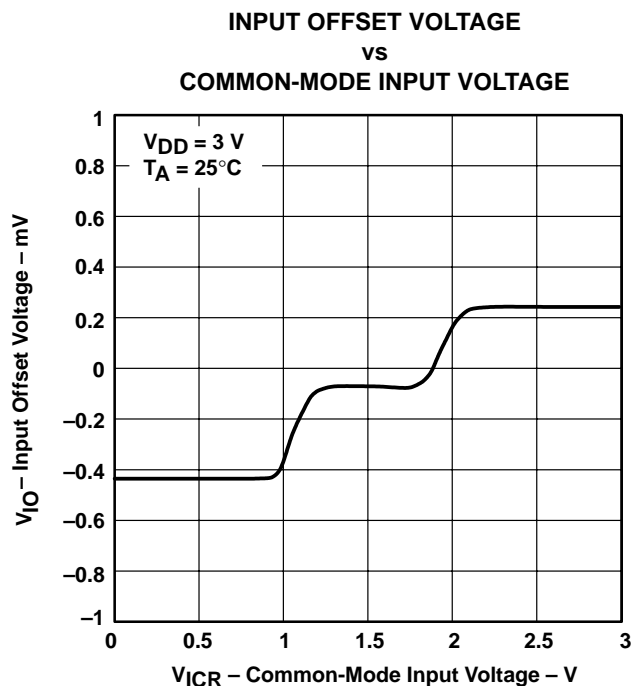


Figure 1

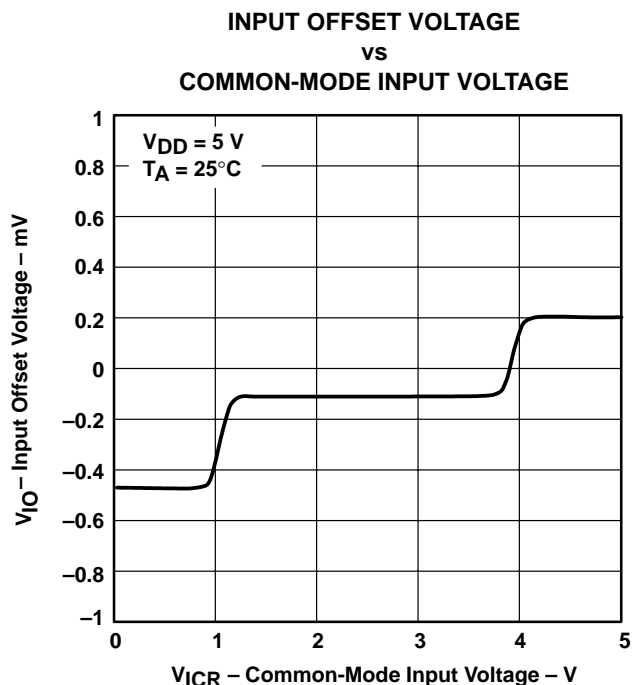


Figure 2

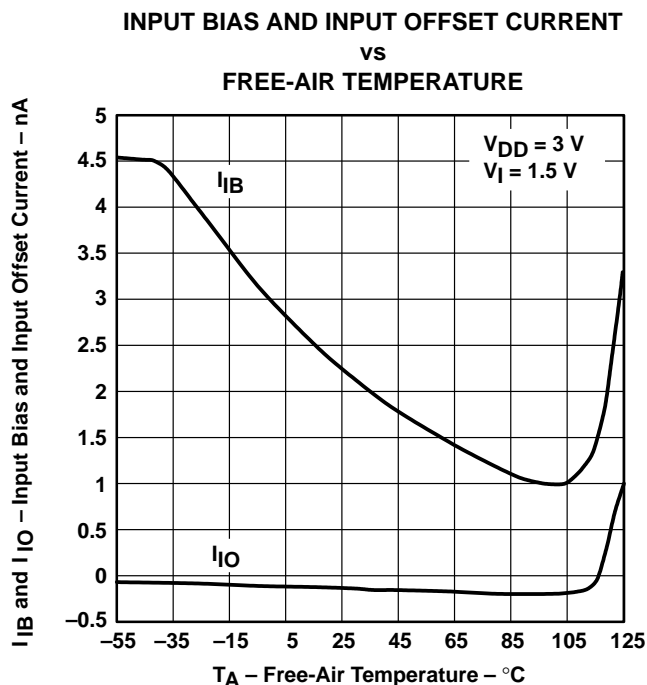


Figure 3

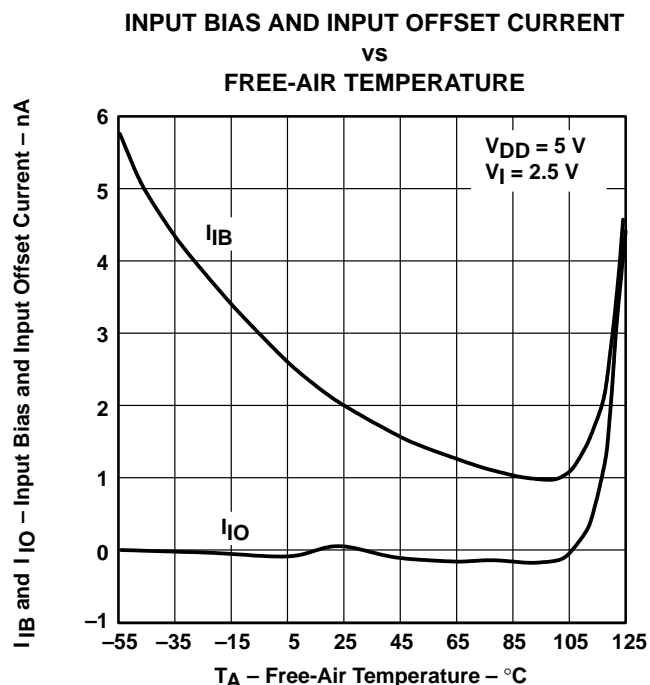


Figure 4

# TYPICAL CHARACTERISTICS

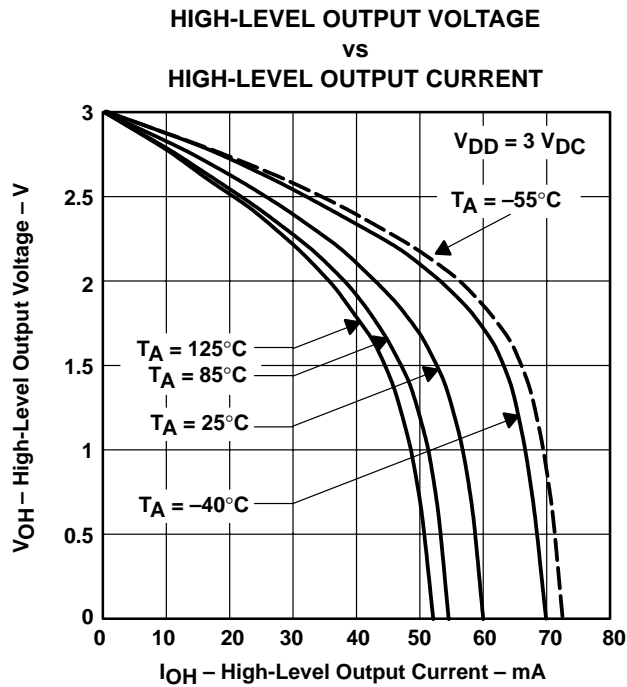


Figure 5

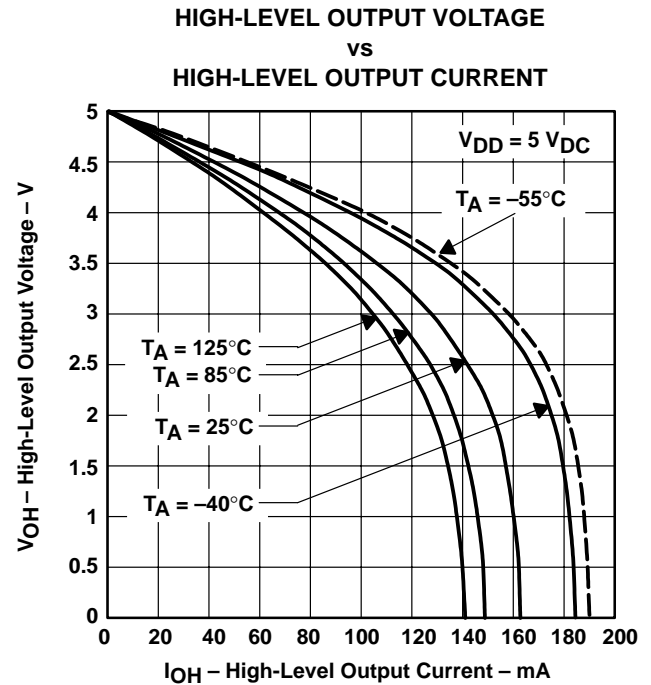


Figure 6

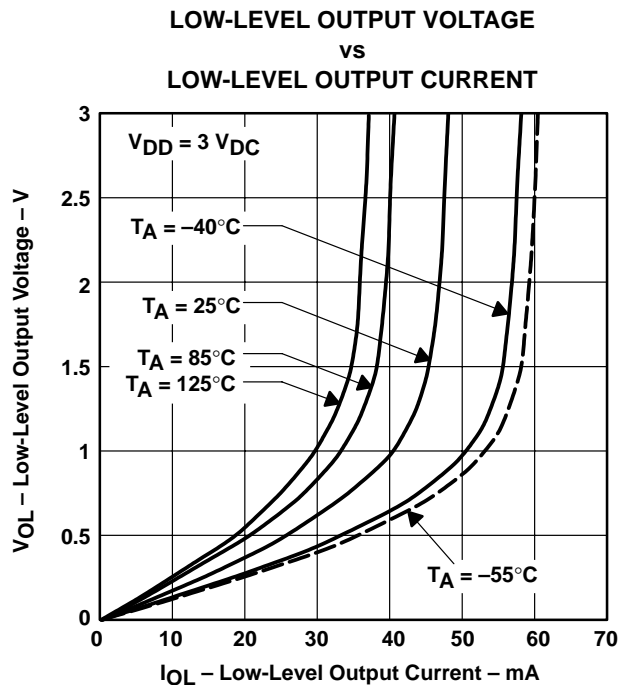


Figure 7

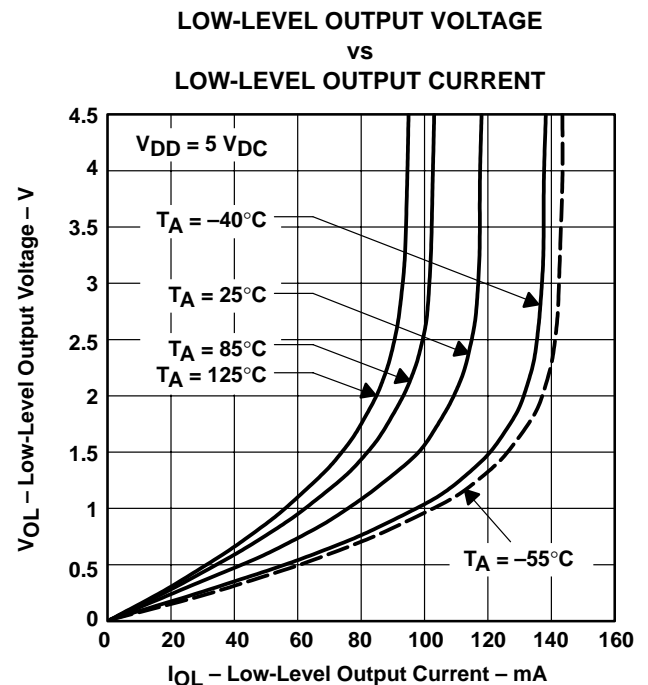


Figure 8

# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA

## FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT

### OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

#### TYPICAL CHARACTERISTICS

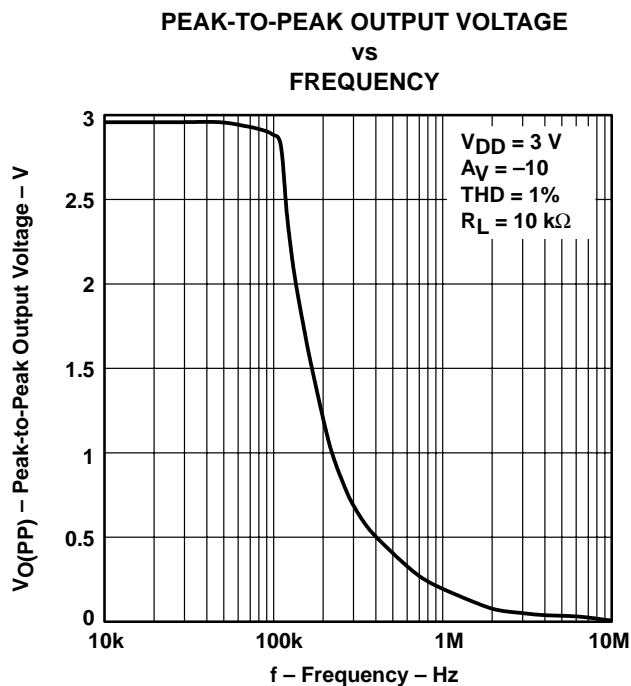


Figure 9

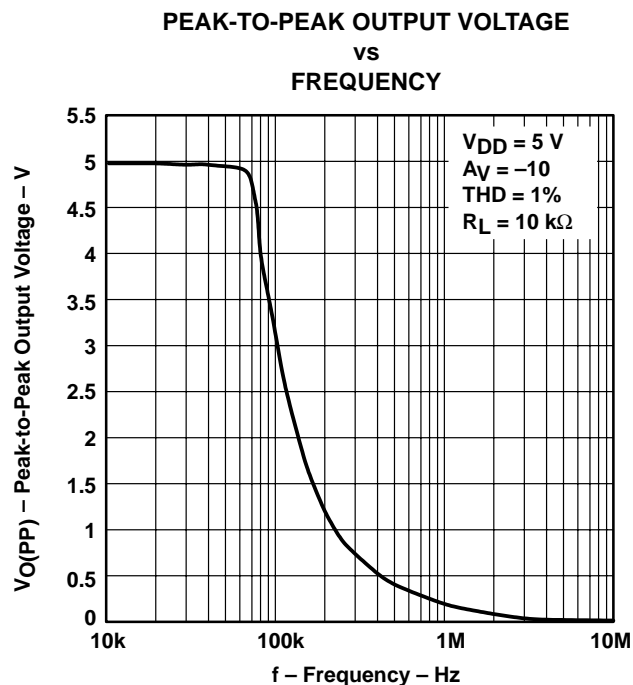


Figure 10

#### OPEN-LOOP GAIN AND PHASE vs FREQUENCY

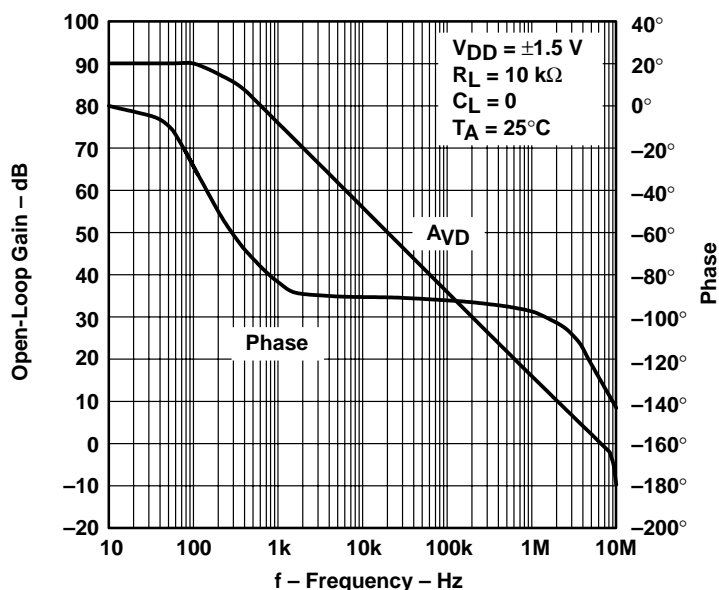


Figure 11

TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA  
FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT  
OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

TYPICAL CHARACTERISTICS

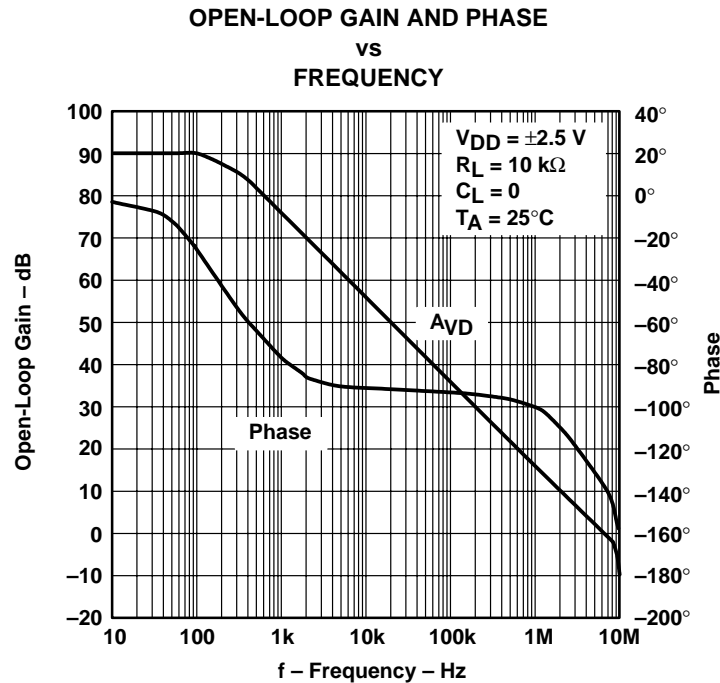


Figure 12

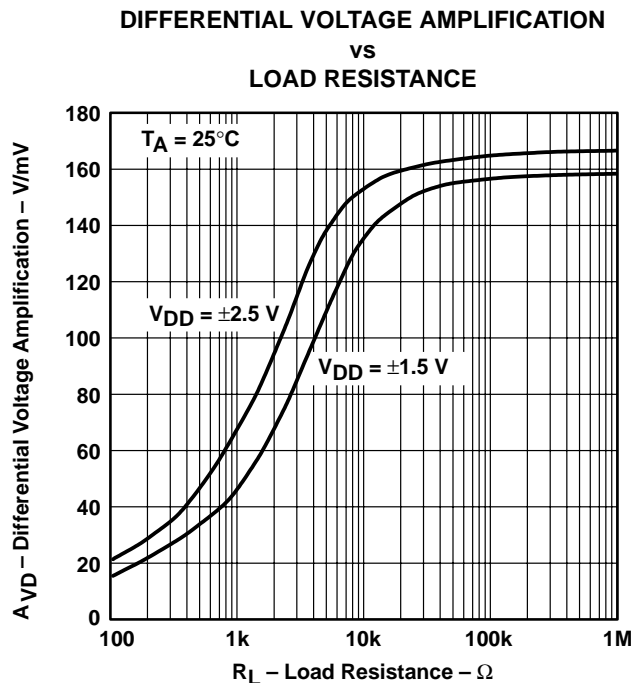


Figure 13

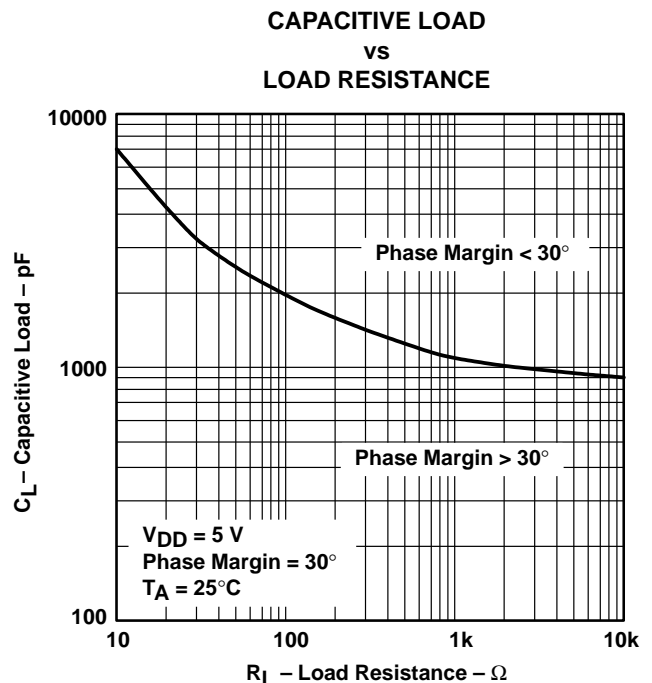


Figure 14

# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA

## FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT

### OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

#### TYPICAL CHARACTERISTICS

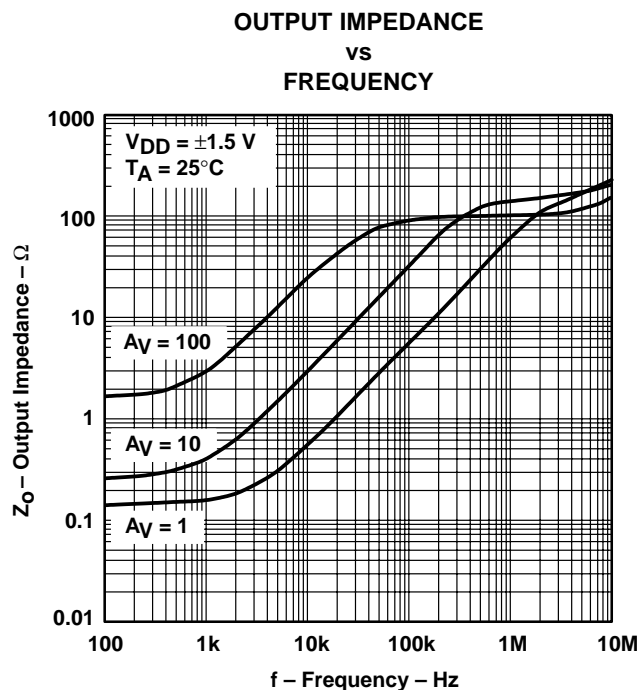


Figure 15

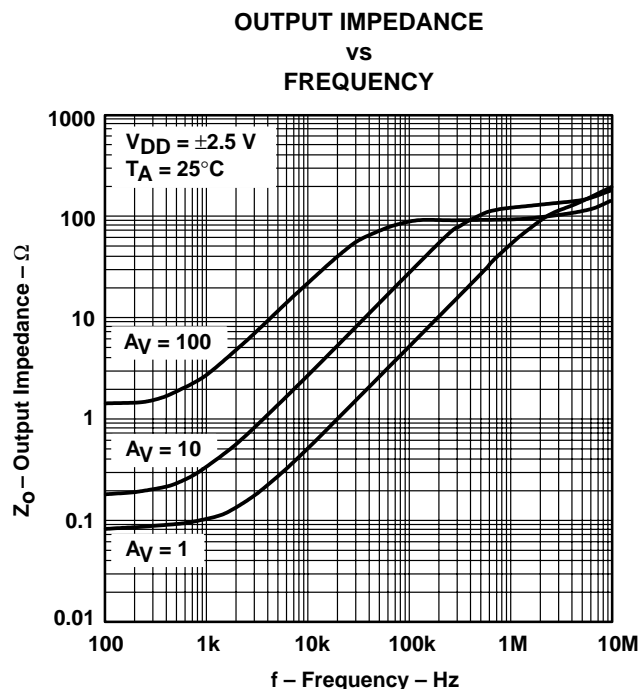


Figure 16

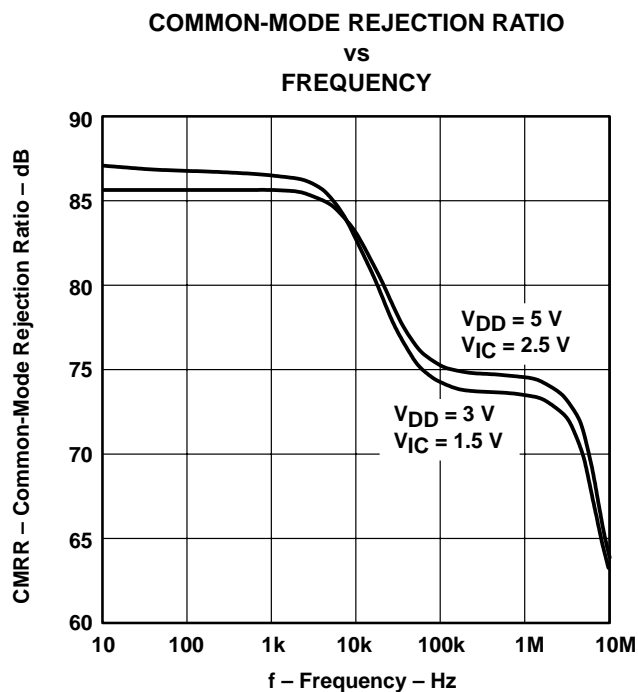


Figure 17



TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA  
FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT  
OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

TYPICAL CHARACTERISTICS

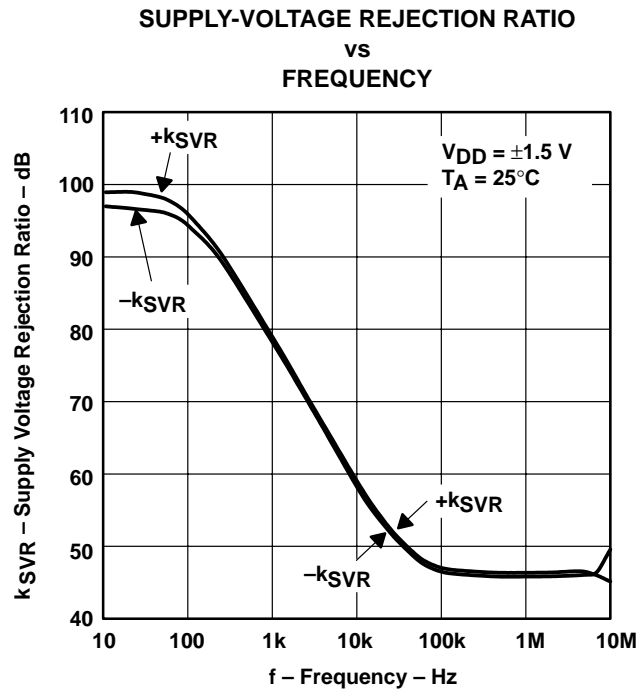


Figure 18

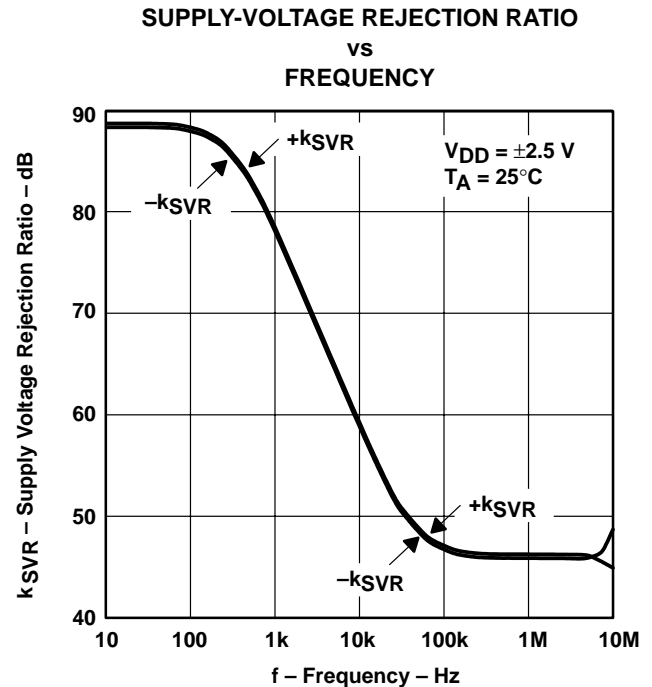


Figure 19

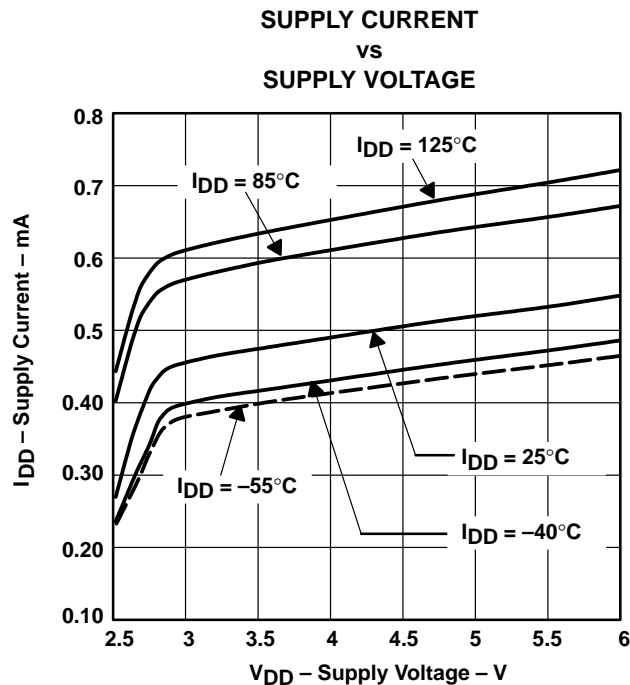


Figure 20

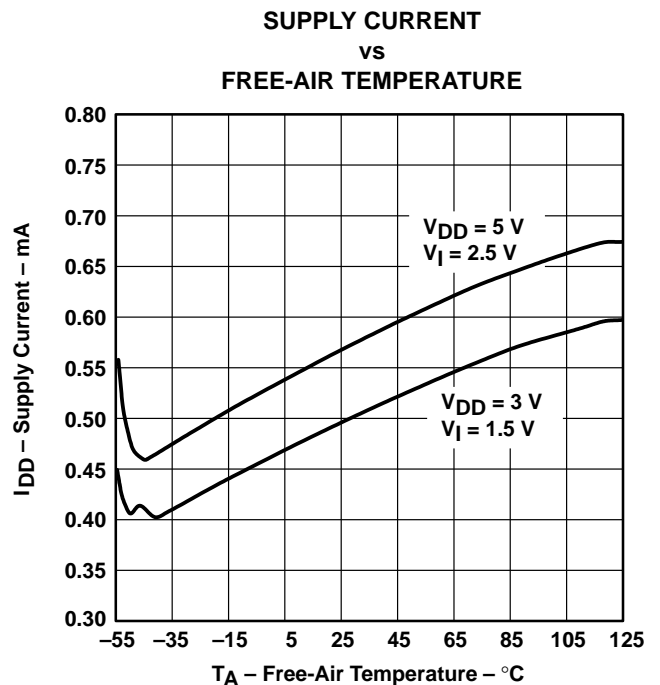


Figure 21

# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

## TYPICAL CHARACTERISTICS

AMPLIFIER WITH A SHUTDOWN PULSE  
TURNON CHARACTERISTICS

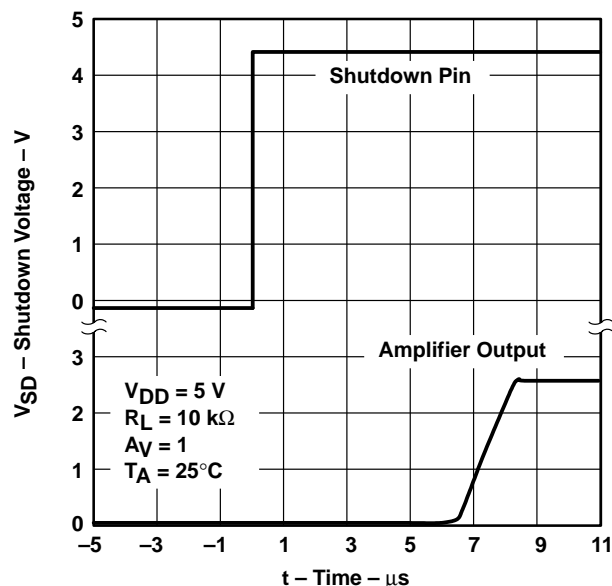


Figure 22

AMPLIFIER WITH A SHUTDOWN PULSE  
TURNOFF CHARACTERISTICS

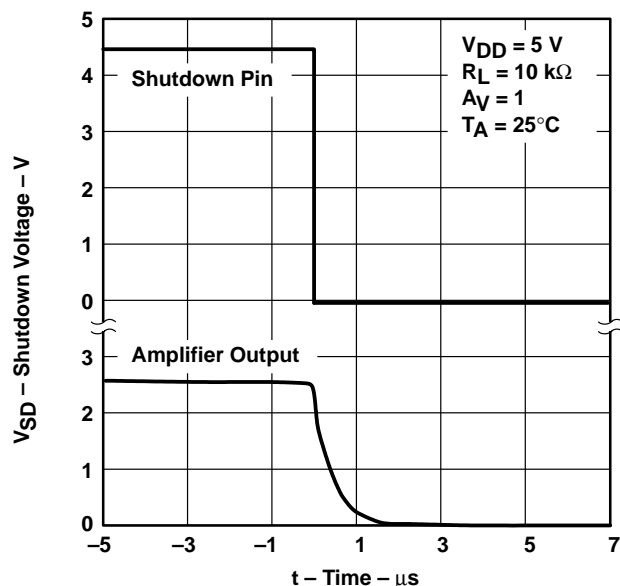


Figure 23

SUPPLY CURRENT WITH A SHUTDOWN PULSE  
TURNON CHARACTERISTICS

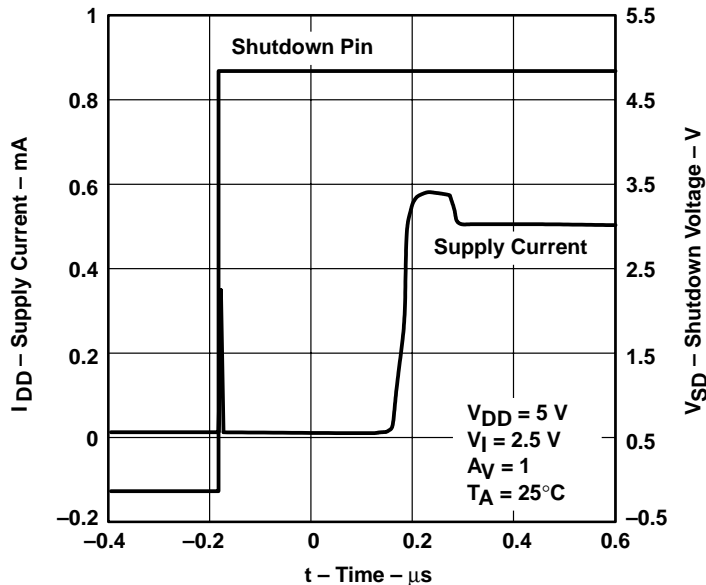


Figure 24

## TYPICAL CHARACTERISTICS

### TURN-OFF SUPPLY CURRENT WITH A SHUTDOWN PULSE

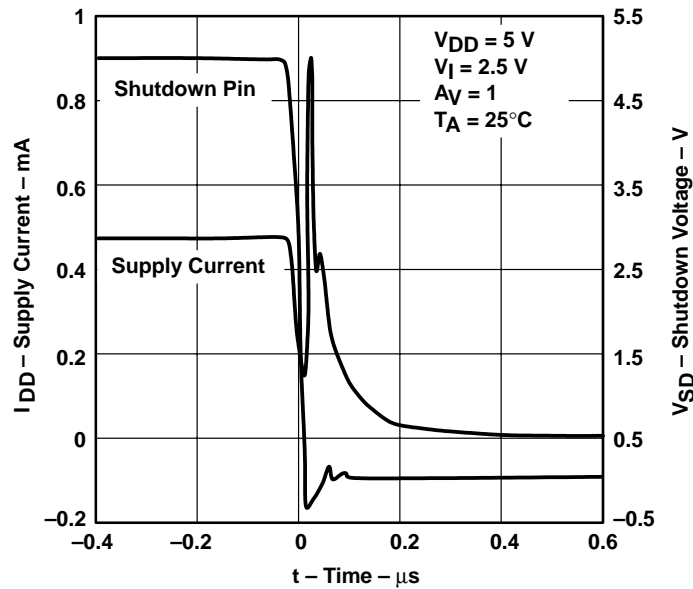


Figure 25

### SHUTDOWN SUPPLY CURRENT vs FREE-AIR TEMPERATURE

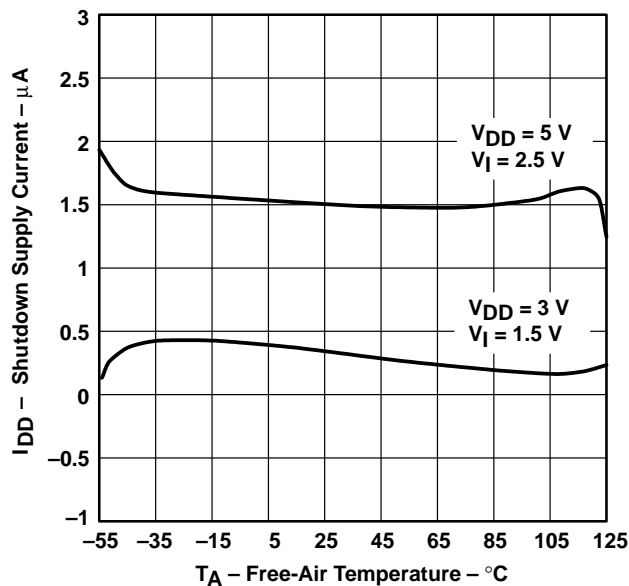


Figure 26

### SLEW RATE vs SUPPLY VOLTAGE

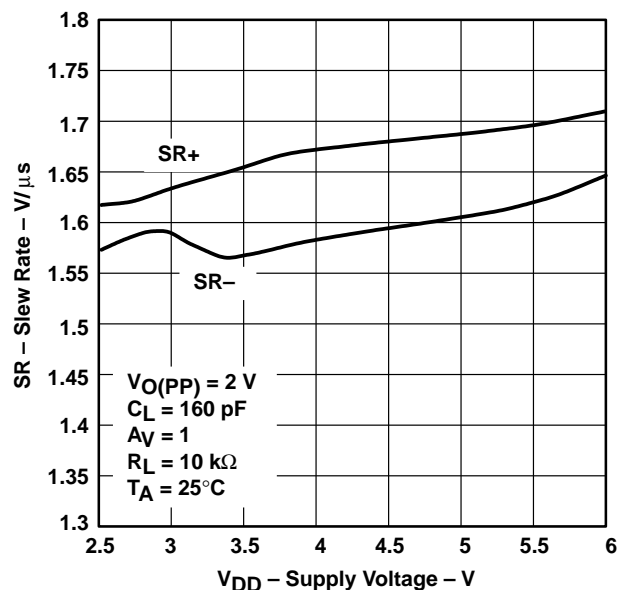


Figure 27

# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA

## FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT

### OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

#### TYPICAL CHARACTERISTICS

EQUIVALENT INPUT NOISE VOLTAGE  
vs  
FREQUENCY

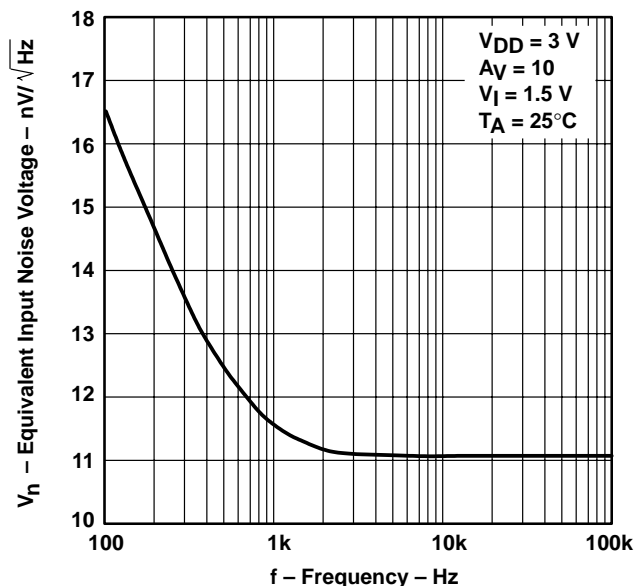


Figure 28

EQUIVALENT INPUT NOISE VOLTAGE  
vs  
FREQUENCY

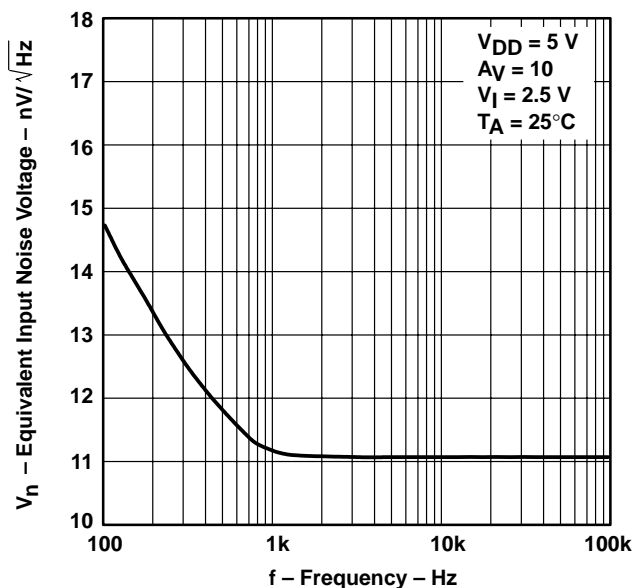


Figure 29

EQUIVALENT INPUT NOISE VOLTAGE  
vs  
COMMON-MODE INPUT VOLTAGE

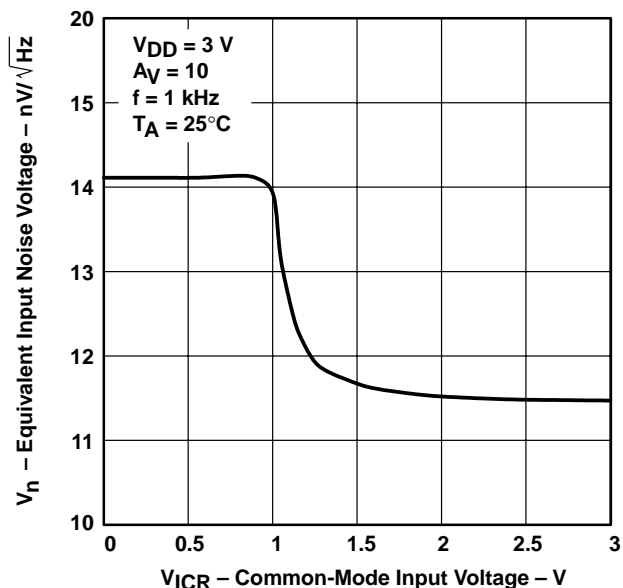


Figure 30

EQUIVALENT INPUT NOISE VOLTAGE  
vs  
COMMON-MODE INPUT VOLTAGE

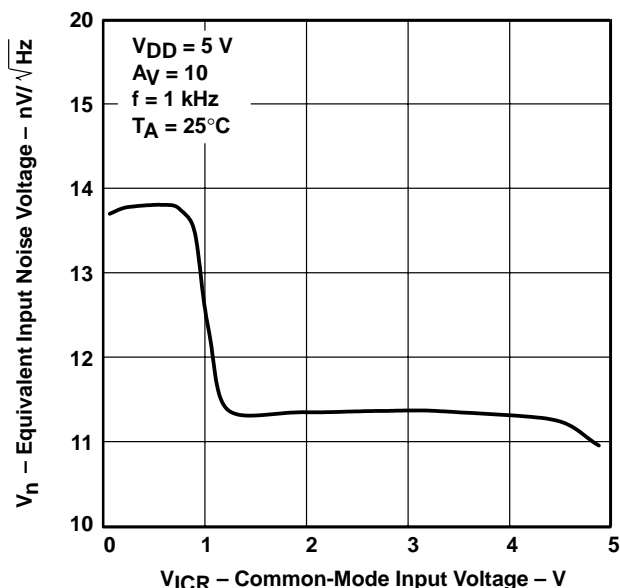


Figure 31

TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA  
FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT  
OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

TYPICAL CHARACTERISTICS

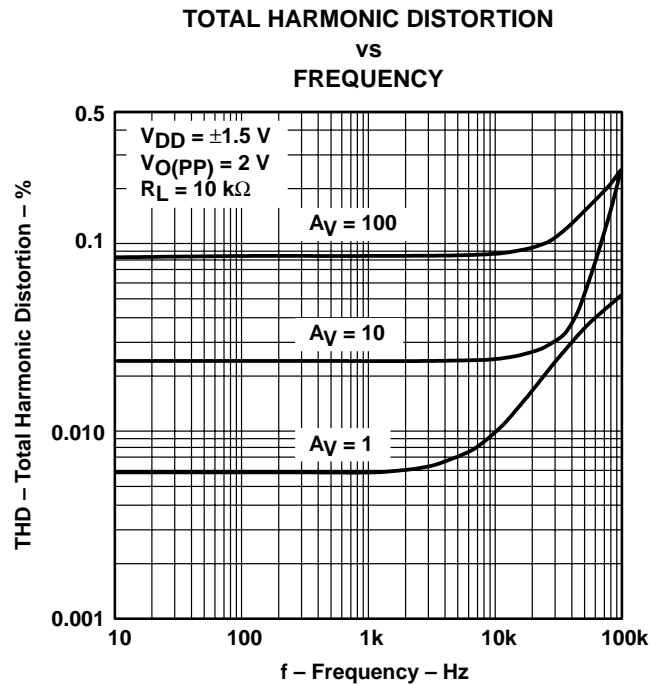


Figure 32

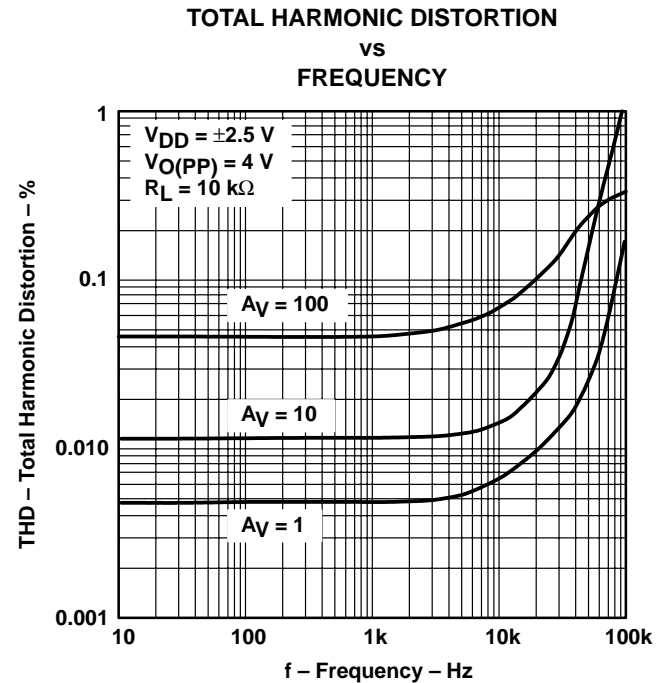


Figure 33

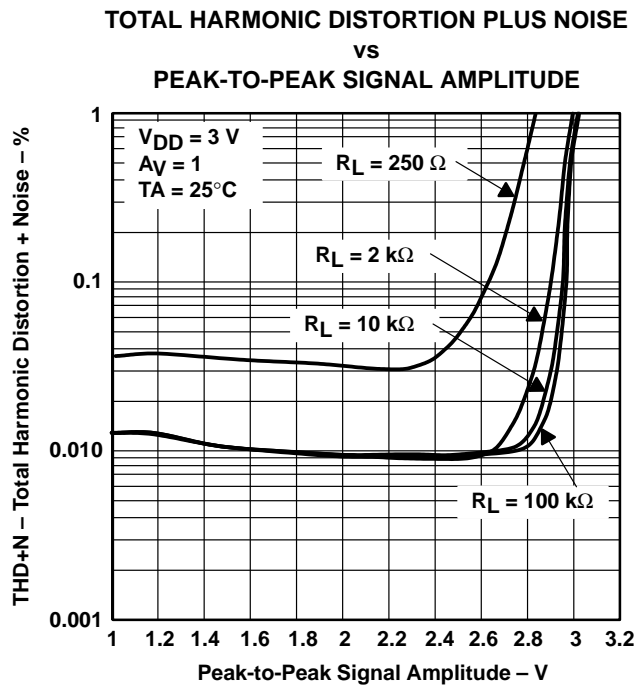


Figure 34

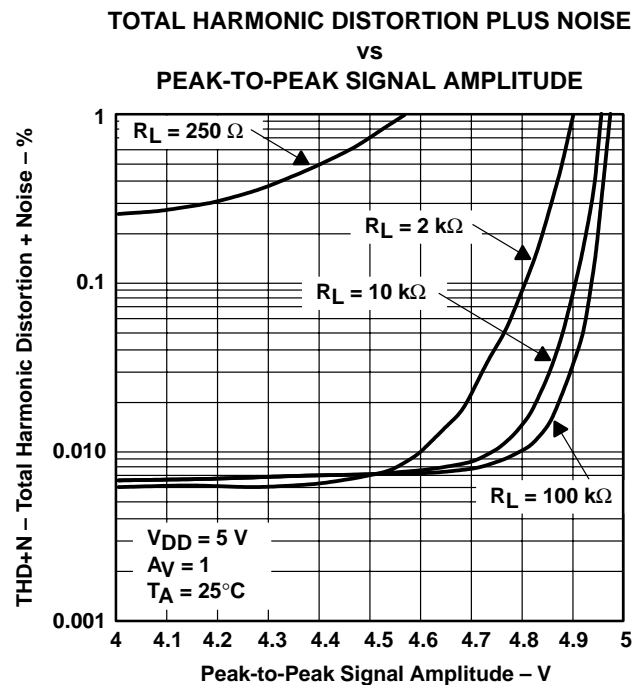


Figure 35

# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA

## FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

### TYPICAL CHARACTERISTICS

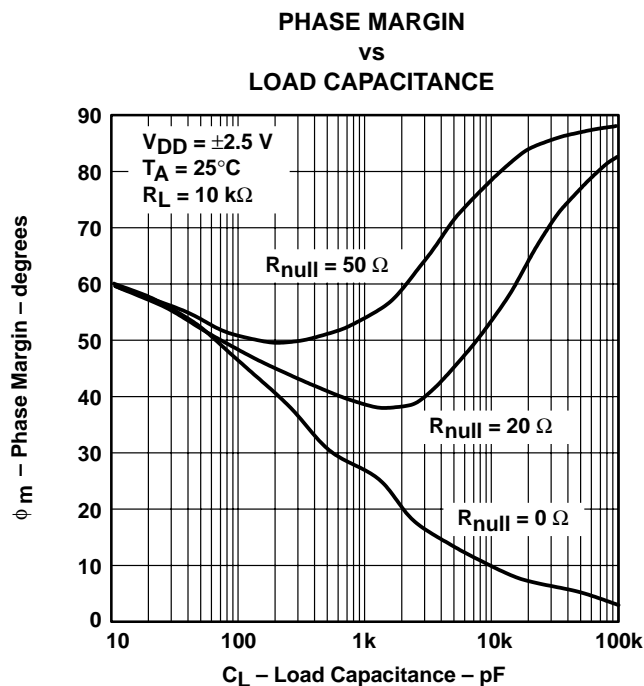


Figure 36

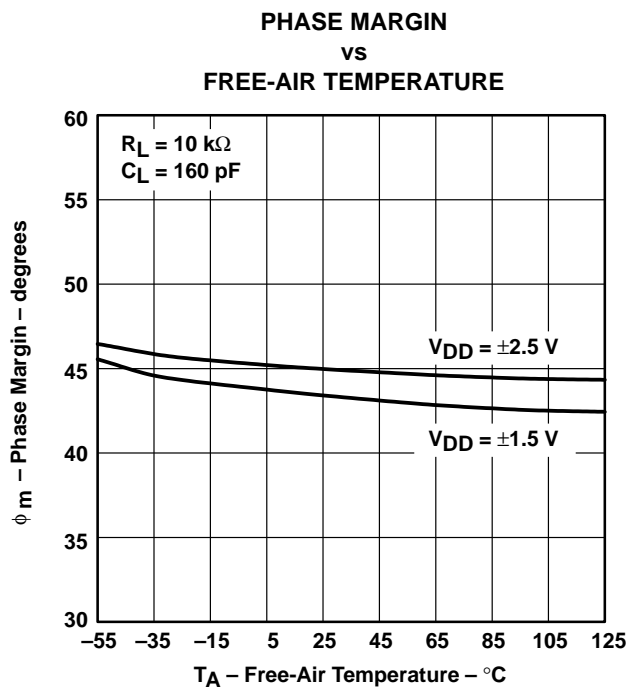


Figure 37

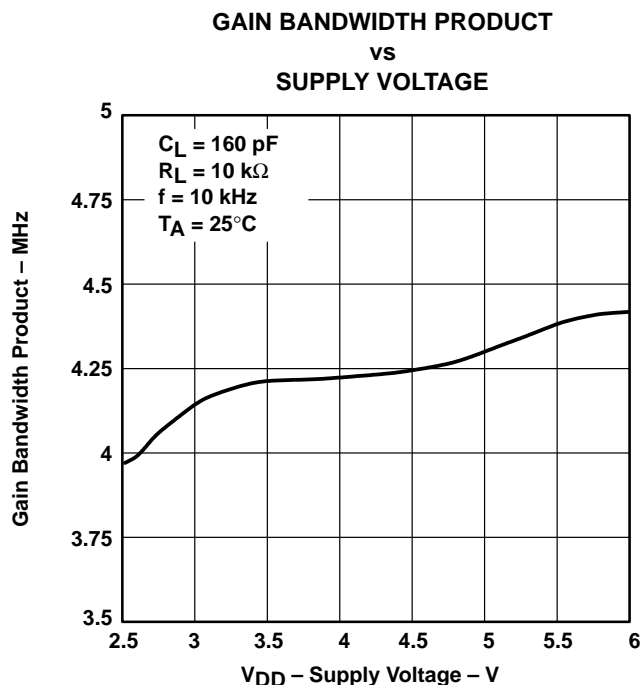


Figure 38

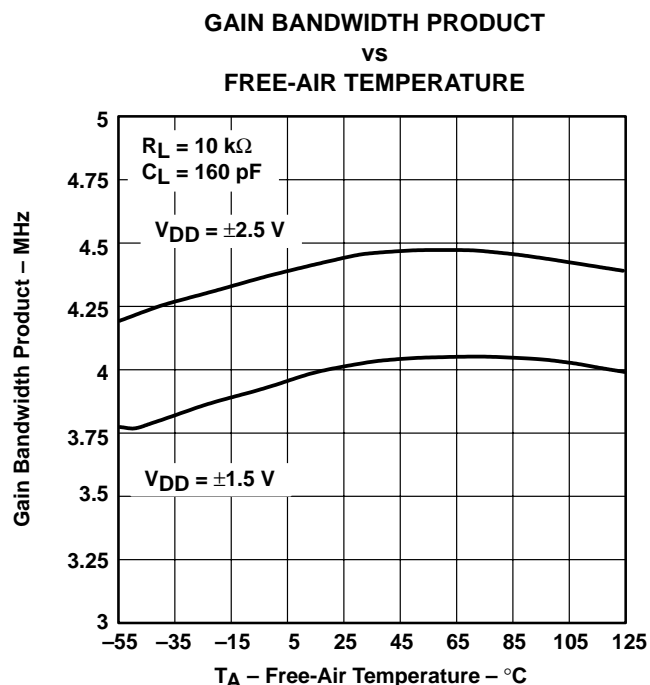


Figure 39

TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA  
 FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT  
 OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

TYPICAL CHARACTERISTICS

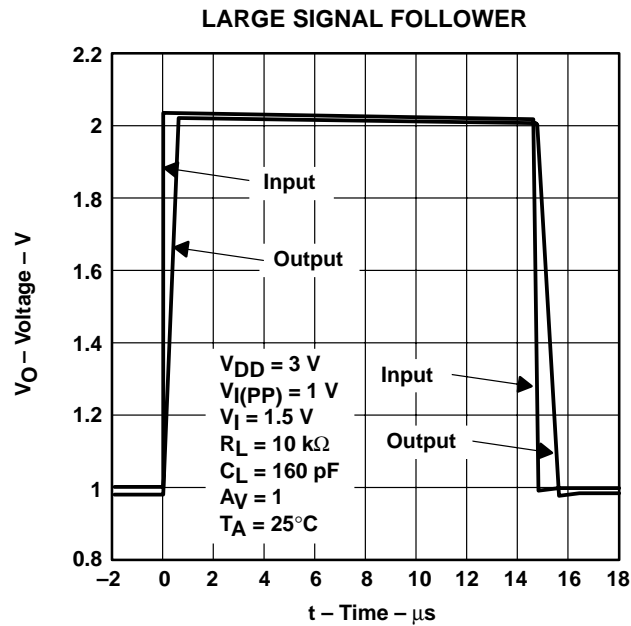


Figure 40

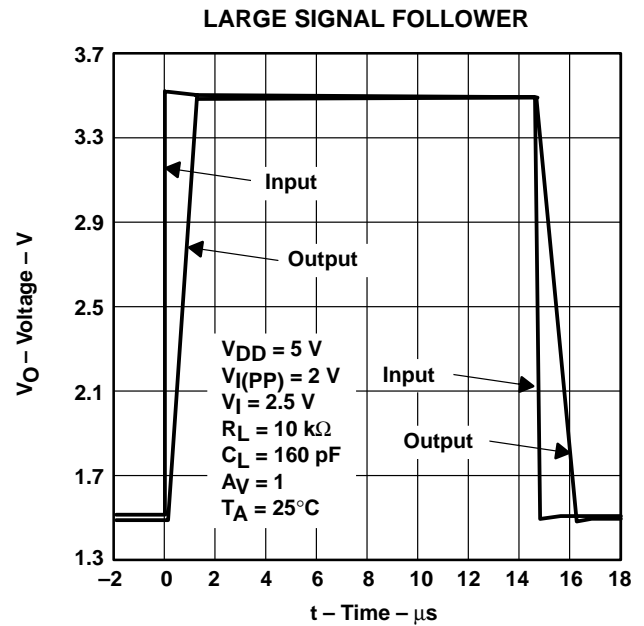


Figure 41

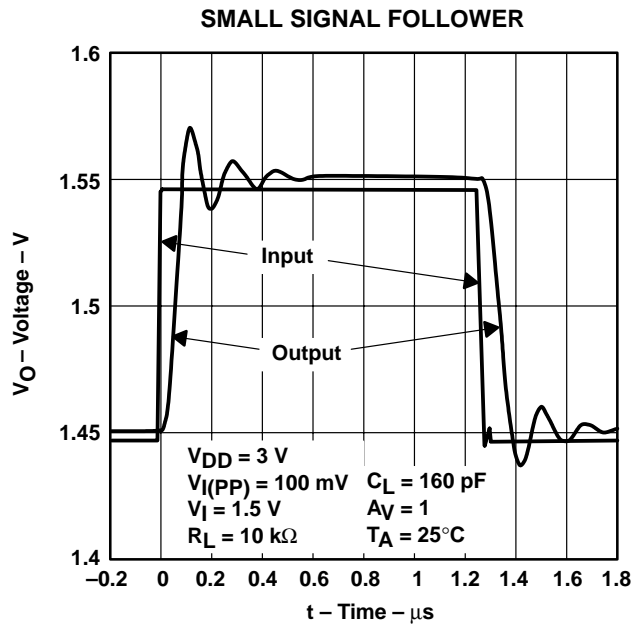


Figure 42

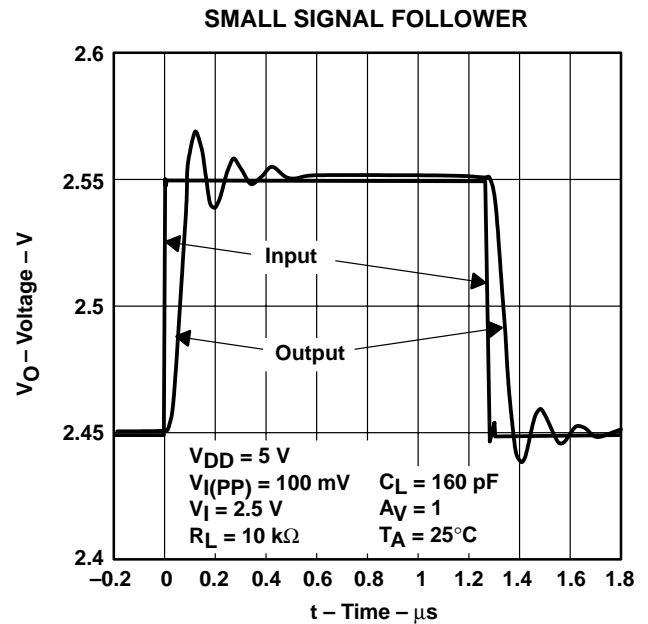


Figure 43

# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA

## FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT

### OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

#### TYPICAL CHARACTERISTICS

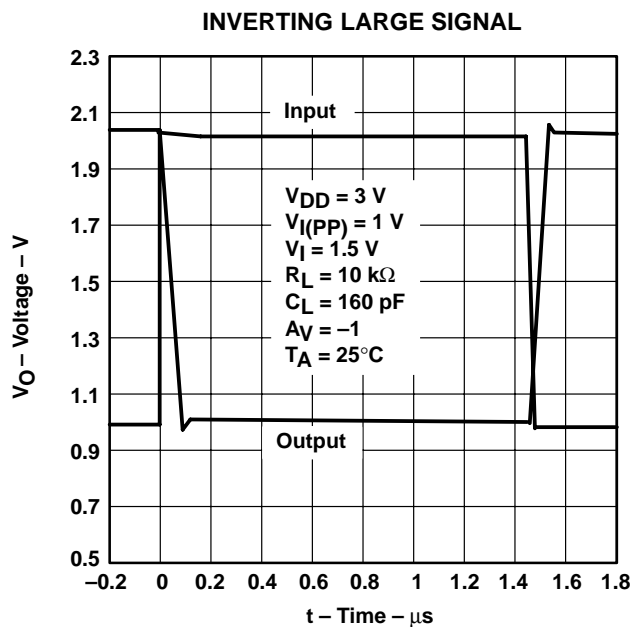


Figure 44

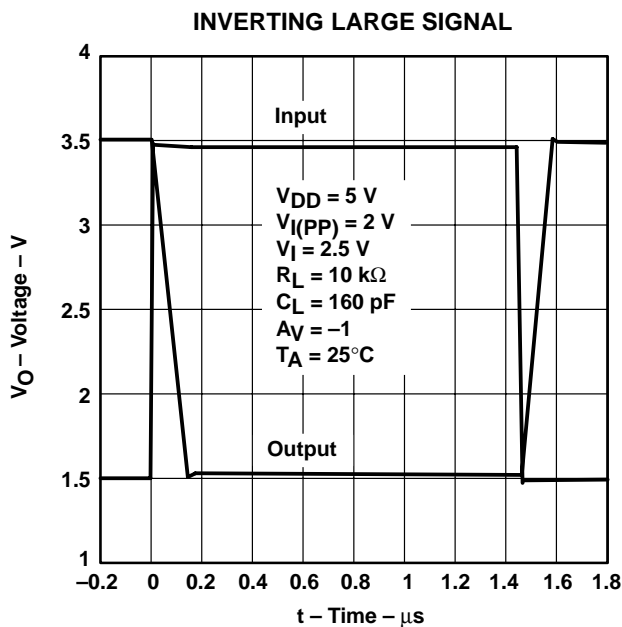


Figure 45

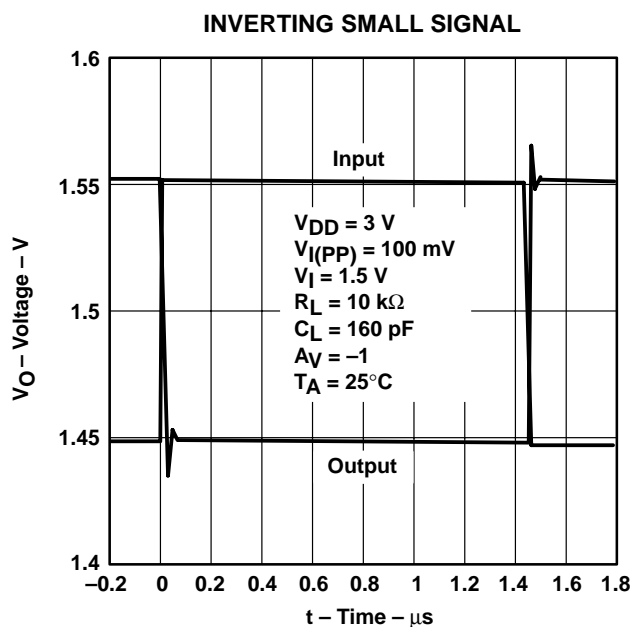


Figure 46

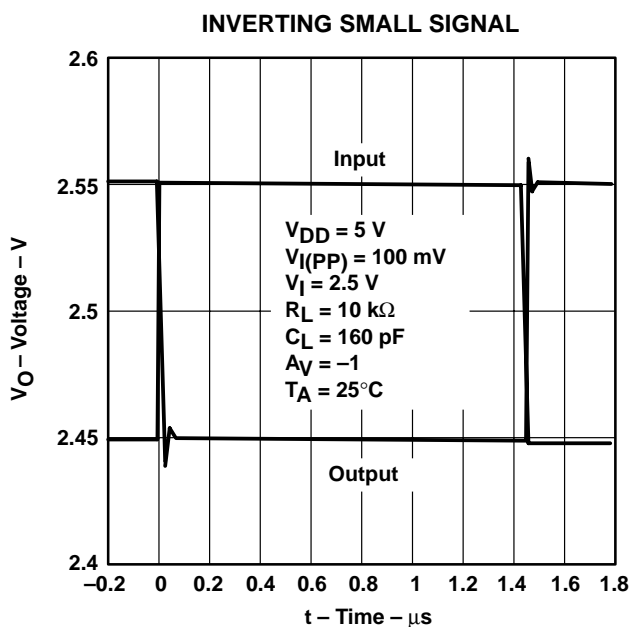


Figure 47



## PARAMETER MEASUREMENT INFORMATION

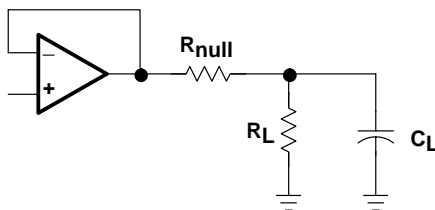


Figure 48

## APPLICATION INFORMATION

### driving a capacitive load

When the amplifier is configured in this manner, capacitive loading directly on the output will decrease the device's phase margin leading to high frequency ringing or oscillations. Therefore, for capacitive loads of greater than 10 pF, it is recommended that a resistor be placed in series ( $R_{NULL}$ ) with the output of the amplifier, as shown in Figure 49. A minimum value of 20  $\Omega$  should work well for most applications.

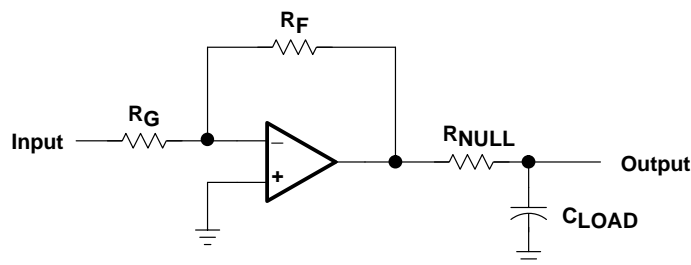


Figure 49. Driving a Capacitive Load

### offset voltage

The output offset voltage, ( $V_{OO}$ ) is the sum of the input offset voltage ( $V_{IO}$ ) and both input bias currents ( $I_{IB}$ ) times the corresponding gains. The following schematic and formula can be used to calculate the output offset voltage:

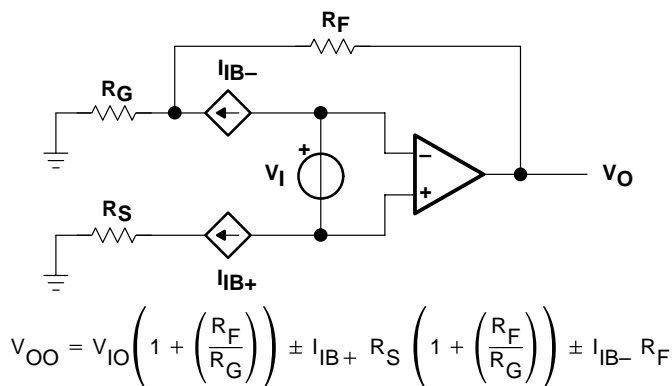


Figure 50. Output Offset Voltage Model

# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA

## FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

### APPLICATION INFORMATION

#### general configurations

When receiving low-level signals, limiting the bandwidth of the incoming signals into the system is often required. The simplest way to accomplish this is to place an RC filter at the noninverting terminal of the amplifier (see Figure 51).

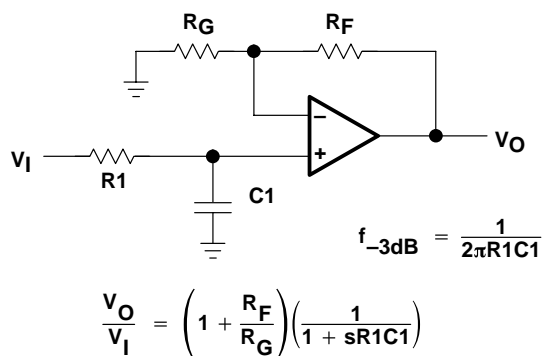


Figure 51. Single-Pole Low-Pass Filter

If even more attenuation is needed, a multiple pole filter is required. The Sallen-Key filter can be used for this task. For best results, the amplifier should have a bandwidth that is 8 to 10 times the filter frequency bandwidth. Failure to do this can result in phase shift of the amplifier.

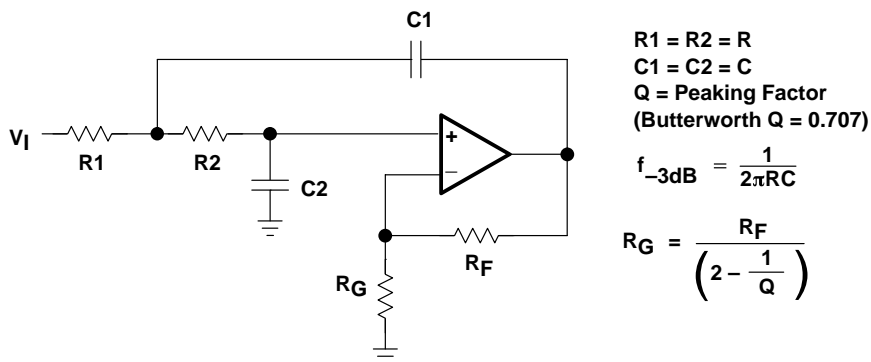


Figure 52. 2-Pole Low-Pass Sallen-Key Filter

## APPLICATION INFORMATION

### shutdown function

Three members of the TLV246x family (TLV2460/3/5) have a shutdown terminal for conserving battery life in portable applications. When the shutdown terminal is tied low, the supply current is reduced to 0.3  $\mu\text{A}/\text{channel}$ , the amplifier is disabled, and the outputs are placed in a high impedance mode. To enable the amplifier, the shutdown terminal can either be left floating or pulled high. When the shutdown terminal is left floating, care should be taken to ensure that parasitic leakage current at the shutdown terminal does not inadvertently place the operational amplifier into shutdown. The shutdown terminal threshold is always referenced to  $V_{DD}/2$ . Therefore, when operating the device with split supply voltages (e.g.  $\pm 2.5\text{ V}$ ), the shutdown terminal needs to be pulled to  $V_{DD-}$  (not GND) to disable the operational amplifier.

The amplifier's output with a shutdown pulse is shown in Figures 22, 23, 24, and 25. The amplifier is powered with a single 5-V supply and configured as a noninverting configuration with a gain of 5. The amplifier turnon and turnoff times are measured from the 50% point of the shutdown pulse to the 50% point of the output waveform. The times for the single, dual, and quad are listed in the data tables.

### circuit layout considerations

To achieve the levels of high performance of the TLV246x, follow proper printed-circuit board design techniques. A general set of guidelines is given in the following.

- Ground planes – It is highly recommended that a ground plane be used on the board to provide all components with a low inductive ground connection. However, in the areas of the amplifier inputs and output, the ground plane can be removed to minimize the stray capacitance.
- Proper power supply decoupling – Use a 6.8- $\mu\text{F}$  tantalum capacitor in parallel with a 0.1- $\mu\text{F}$  ceramic capacitor on each supply terminal. It may be possible to share the tantalum among several amplifiers depending on the application, but a 0.1- $\mu\text{F}$  ceramic capacitor should always be used on the supply terminal of every amplifier. In addition, the 0.1- $\mu\text{F}$  capacitor should be placed as close as possible to the supply terminal. As this distance increases, the inductance in the connecting trace makes the capacitor less effective. The designer should strive for distances of less than 0.1 inches between the device power terminals and the ceramic capacitors.
- Sockets – Sockets can be used but are not recommended. The additional lead inductance in the socket pins will often lead to stability problems. Surface-mount packages soldered directly to the printed-circuit board is the best implementation.
- Short trace runs/compact part placements – Optimum high performance is achieved when stray series inductance has been minimized. To realize this, the circuit layout should be made as compact as possible, thereby minimizing the length of all trace runs. Particular attention should be paid to the inverting input of the amplifier. Its length should be kept as short as possible. This will help to minimize stray capacitance at the input of the amplifier.
- Surface-mount passive components – Using surface-mount passive components is recommended for high performance amplifier circuits for several reasons. First, because of the extremely low lead inductance of surface-mount components, the problem with stray series inductance is greatly reduced. Second, the small size of surface-mount components naturally leads to a more compact layout thereby minimizing both stray inductance and capacitance. If leaded components are used, it is recommended that the lead lengths be kept as short as possible.

# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

## APPLICATION INFORMATION

### general power dissipation considerations

For a given  $\theta_{JA}$ , the maximum power dissipation is shown in Figure 53 and is calculated by the following formula:

$$P_D = \left( \frac{T_{MAX} - T_A}{\theta_{JA}} \right)$$

Where:

$P_D$  = Maximum power dissipation of THS246x IC (watts)

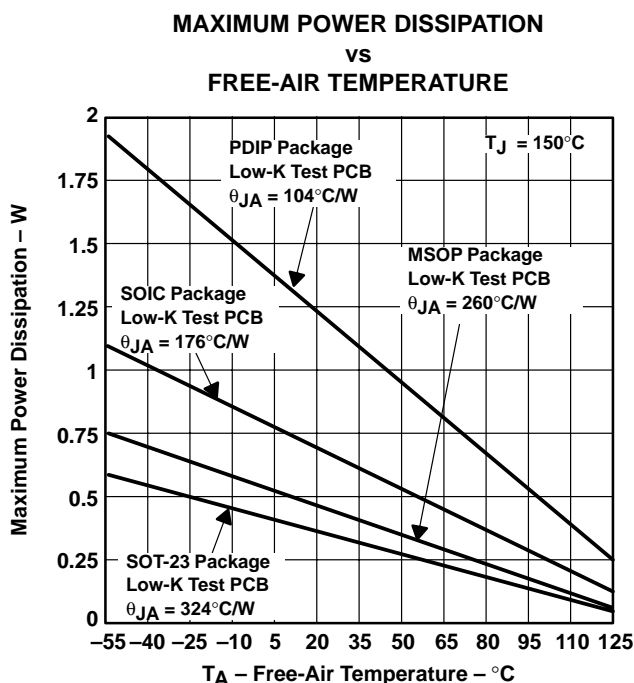
$T_{MAX}$  = Absolute maximum junction temperature (150°C)

$T_A$  = Free-ambient air temperature (°C)

$\theta_{JA} = \theta_{JC} + \theta_{CA}$

$\theta_{JC}$  = Thermal coefficient from junction to case

$\theta_{CA}$  = Thermal coefficient from case to ambient air (°C/W)



NOTE A: Results are with no air flow and using JEDEC Standard Low-K test PCB.

**Figure 53. Maximum Power Dissipation vs Free-Air Temperature**

## SLOS220I – JULY 1998 – REVISED MARCH 2001

## macromodel information

- Maximum positive output voltage swing
- Maximum negative output voltage swing
- Slew rate
- Quiescent power dissipation
- Input bias current
- Open-loop voltage amplification
- Unity-gain frequency
- Common-mode rejection ratio
- Phase margin
- DC output resistance
- AC output resistance
- Short-circuit output current limit

RD1	3	11	2.8964E3
RD2	3	12	2.8964E3
R01	8	5	5.6000
R02	7	99	6.2000
RP	3	4	8.9127
RSS	10	99	10.610E6
VB	9	0	DC 0
VC	3	53	DC .7836
VE	54	4	DC .7436
VLIM	7	8	DC 0
VLP	91	0	DC 117
VLN	0	92	DC 117
.MODEL DX D (IS=800.00E-18)			
.MODEL DY D (IS=800.00E-18 Rs = 1m Cjo=10p)			
.MODEL JX1 NJF (IS=1.0000E-12 BETA=6.3239E-3			
+ VTO=-1)			
.MODEL JX2 NJF (IS=1.0000E-12 BETA=6.3239E-3			
+ VTO=-1)			
.ENDS			

*P*Spice and *P*arts are trademarks of MicroSim Corporation.

# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA

## FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT

## OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

### macromodel information (continued)

.subckt TLV_246Y 1 2 3 4 5 6	rp	3	71	8.9127
c1 11 12 2.4603E-12	rss	10	99	10.610E6
c2 72 7 10.000E-12	rs1	6	4	1G
css 10 99 443.21E-15	rs2	6	4	1G
dc 70 53 dy	rs3	6	4	1G
de 54 70 dy	rs4	6	4	1G
dlp 90 91 dx	s1	71	4	6 4 s1x
dln 92 90 dx	s2	70	5	6 4 s1x
dp 4 3 dx	s3	10	74	6 4 s1x
egnd 99 0 poly(2) (3,0) (4,0) 0 .5 .5	s4	74	4	6 4 s2x
fb 7 99 poly(5) vb vc ve vlp vln 0	vb	9	0	dc 0
21.600E6 -1E3 1E3 22E6 -22E6	vc	3	53	dc .7836
ga 72 0 11 12 345.26E-6	ve	54	4	dc .7436
gcm 0 72 10 99 15.422E-9	vlim	7	8	dc 0
iss 74 4 dc 18.850E-6	vlp	91	0	dc 117
hlim 90 0 vlim 1K	vln	0	92	dc 117
j1 11 2 10 jx1	.model dx D(Is=800.00E-18)			
j2 12 1 10 jx2	.model dy D(Is=800.00E-18 Rs=1m Cjo=10p)			
r2 72 9 100.00E3	.model jx1 NJF(Is=1.0000E-12 Beta=6.3239E-3 Vto=-1)			
rd1 3 11 2.8964E3	.model jx2 NJF(Is=1.0000E-12 Beta=6.3239E-3 Vto=-1)			
rd2 3 12 2.8964E3	.model s1x VSWITCH(Roff=1E8 Ron=1.0 Voff=2.5 Von=0.0)			
ro1 8 70 5.6000	.model s2x VSWITCH(Roff=1E8 Ron=1.0 Voff=0 Von=2.5)			
ro2 7 99 6.2000	.ends			

Figure 54. Boyle Macromodels and Subcircuit (Continued)

**TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA**  
**FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT**  
**OPERATIONAL AMPLIFIERS WITH SHUTDOWN**

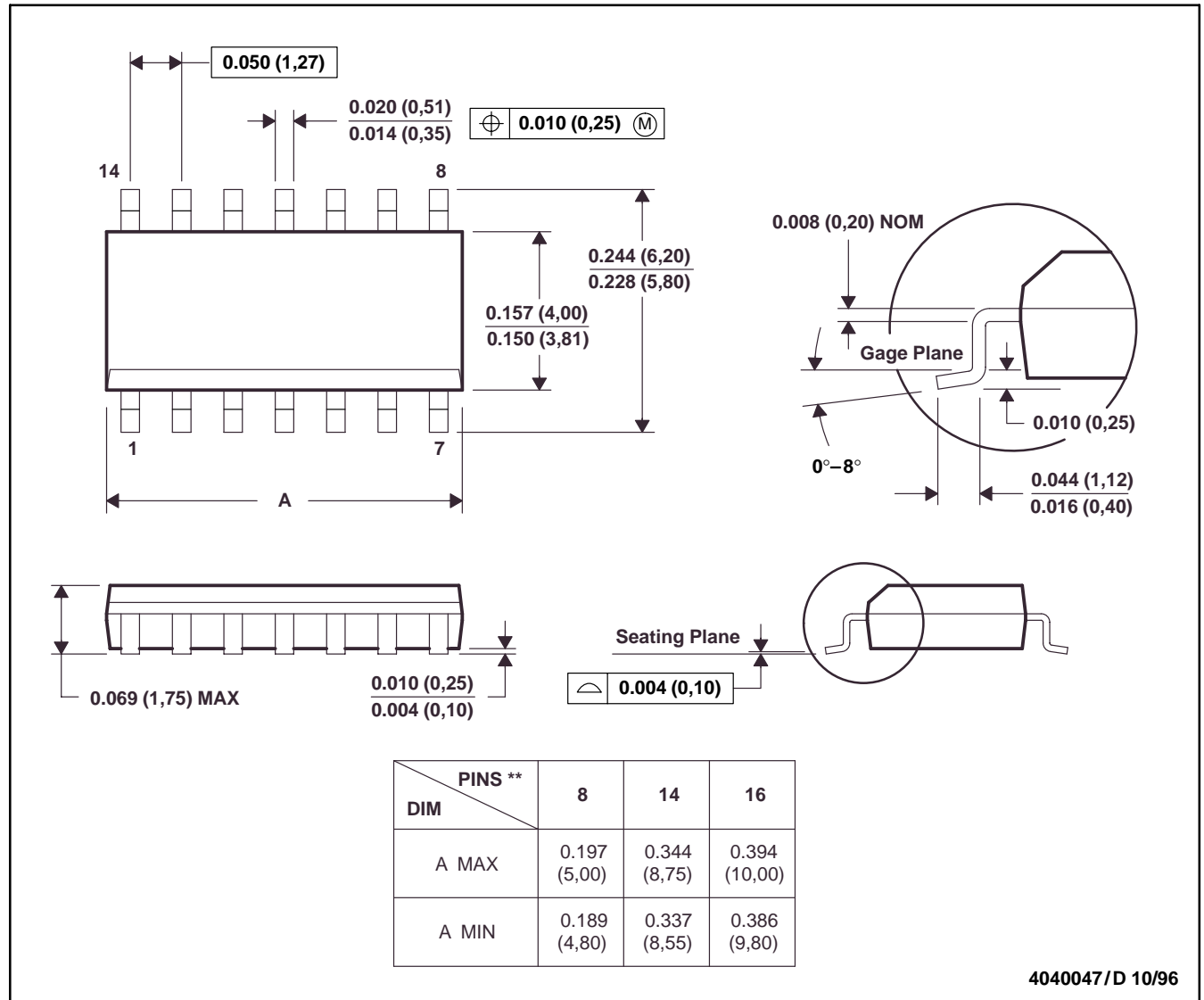
SLOS220I – JULY 1998 – REVISED MARCH 2001

**MECHANICAL DATA**

**D (R-PDSO-G\*\*)**

**PLASTIC SMALL-OUTLINE PACKAGE**

**14 PIN SHOWN**



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).  
 D. Falls within JEDEC MS-012

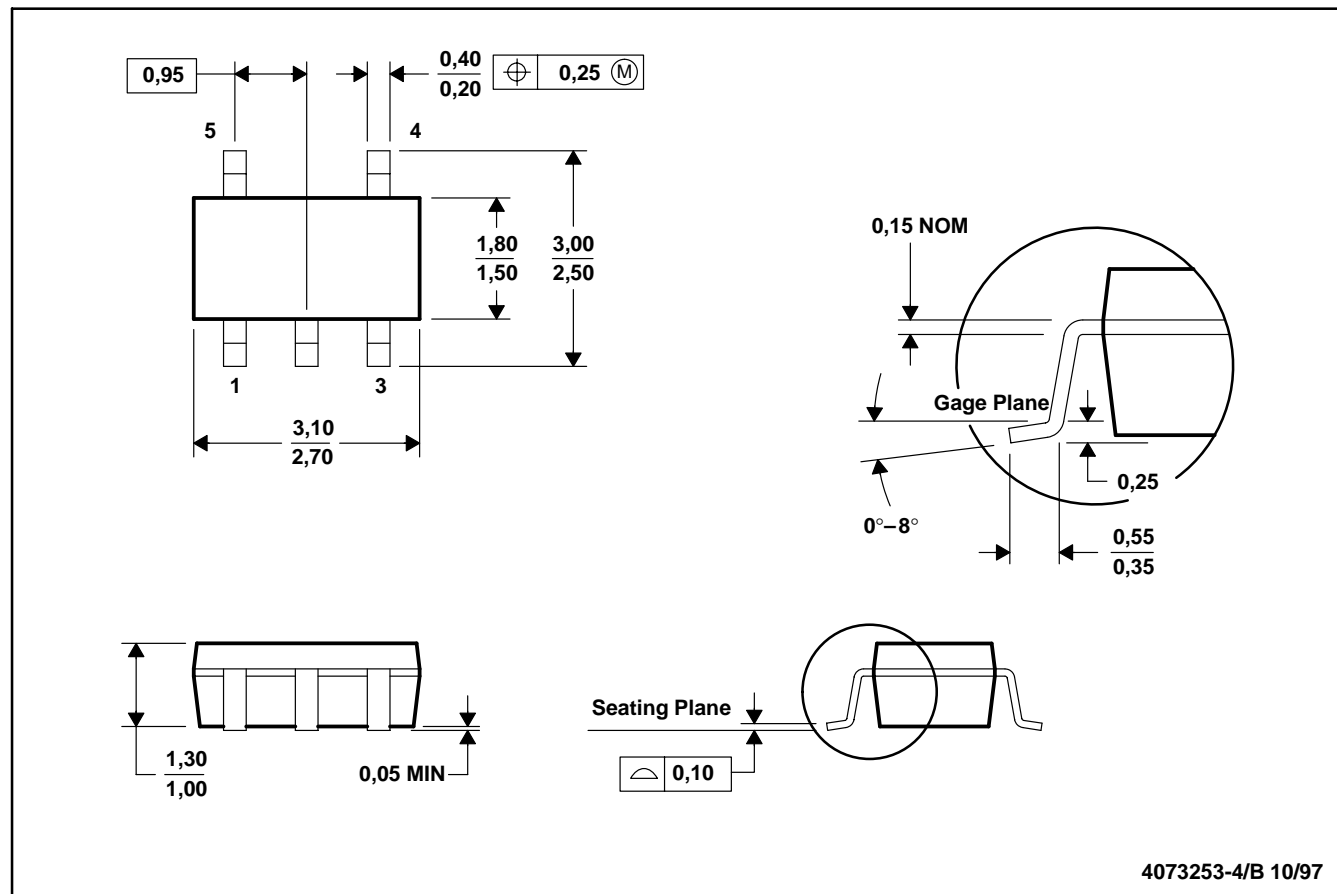
**TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA**  
**FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT**  
**OPERATIONAL AMPLIFIERS WITH SHUTDOWN**

SLOS220I – JULY 1998 – REVISED MARCH 2001

**MECHANICAL DATA**

**DBV (R-PDSO-G5)**

**PLASTIC SMALL-OUTLINE PACKAGE**



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions include mold flash or protrusion.



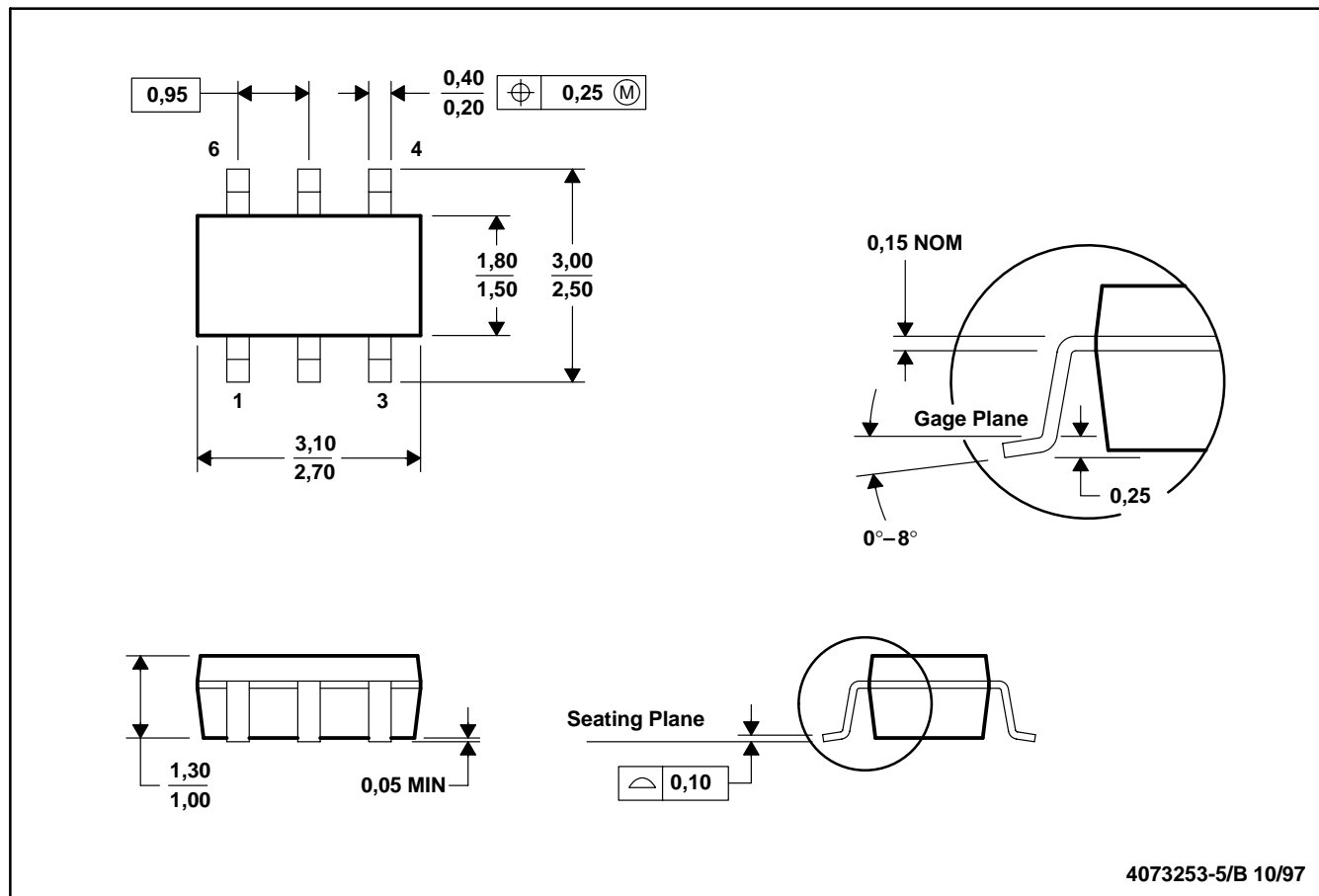
TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA  
FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT  
OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

MECHANICAL DATA

DBV (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.  
B. This drawing is subject to change without notice.  
C. Body dimensions include mold flash or protrusion.

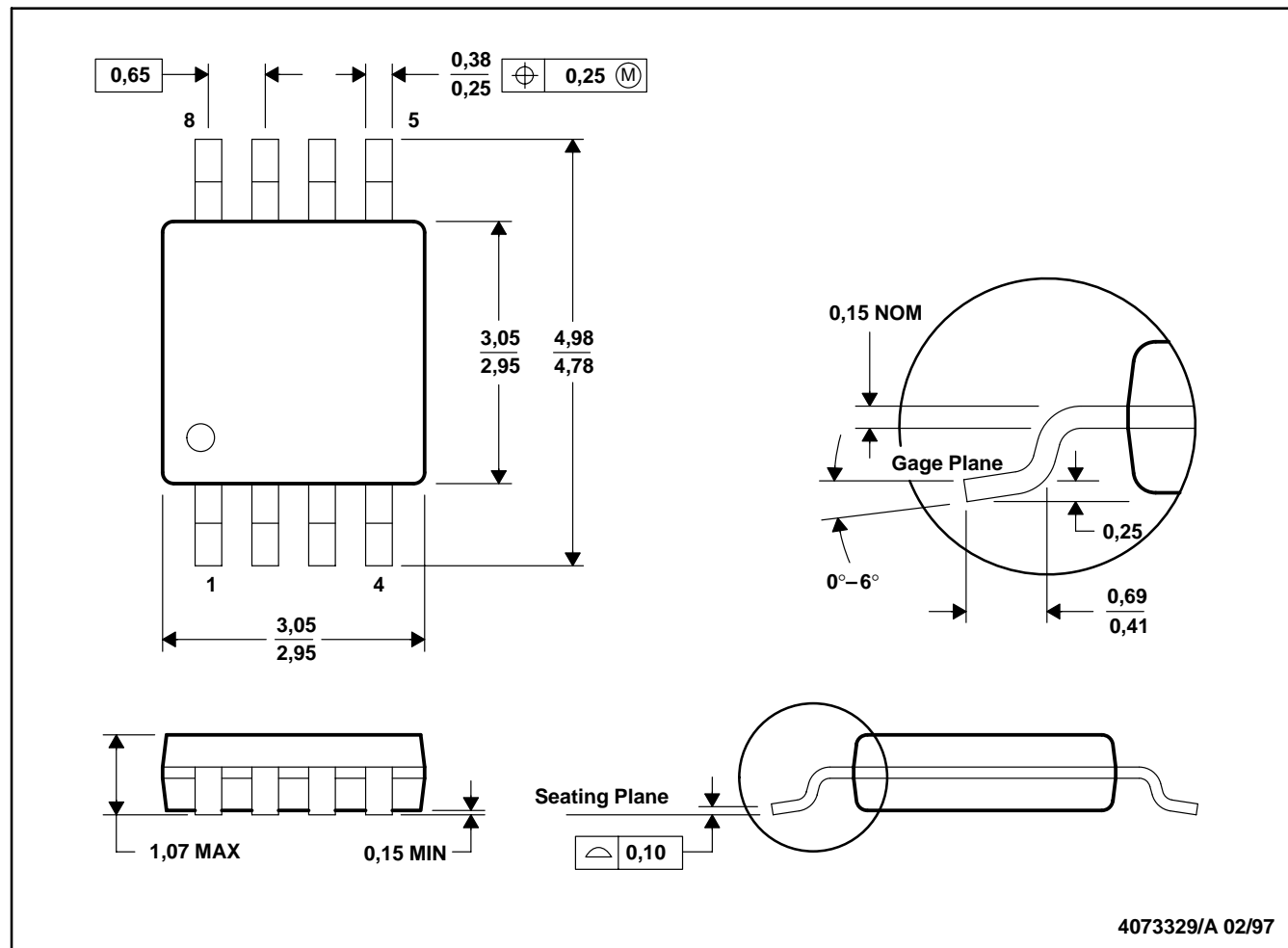
**TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA**  
**FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT**  
**OPERATIONAL AMPLIFIERS WITH SHUTDOWN**

SLOS220I – JULY 1998 – REVISED MARCH 2001

**MECHANICAL DATA**

**DGK (R-PDSO-G8)**

**PLASTIC SMALL-OUTLINE PACKAGE**



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion.  
 D. Falls within JEDEC MO-187

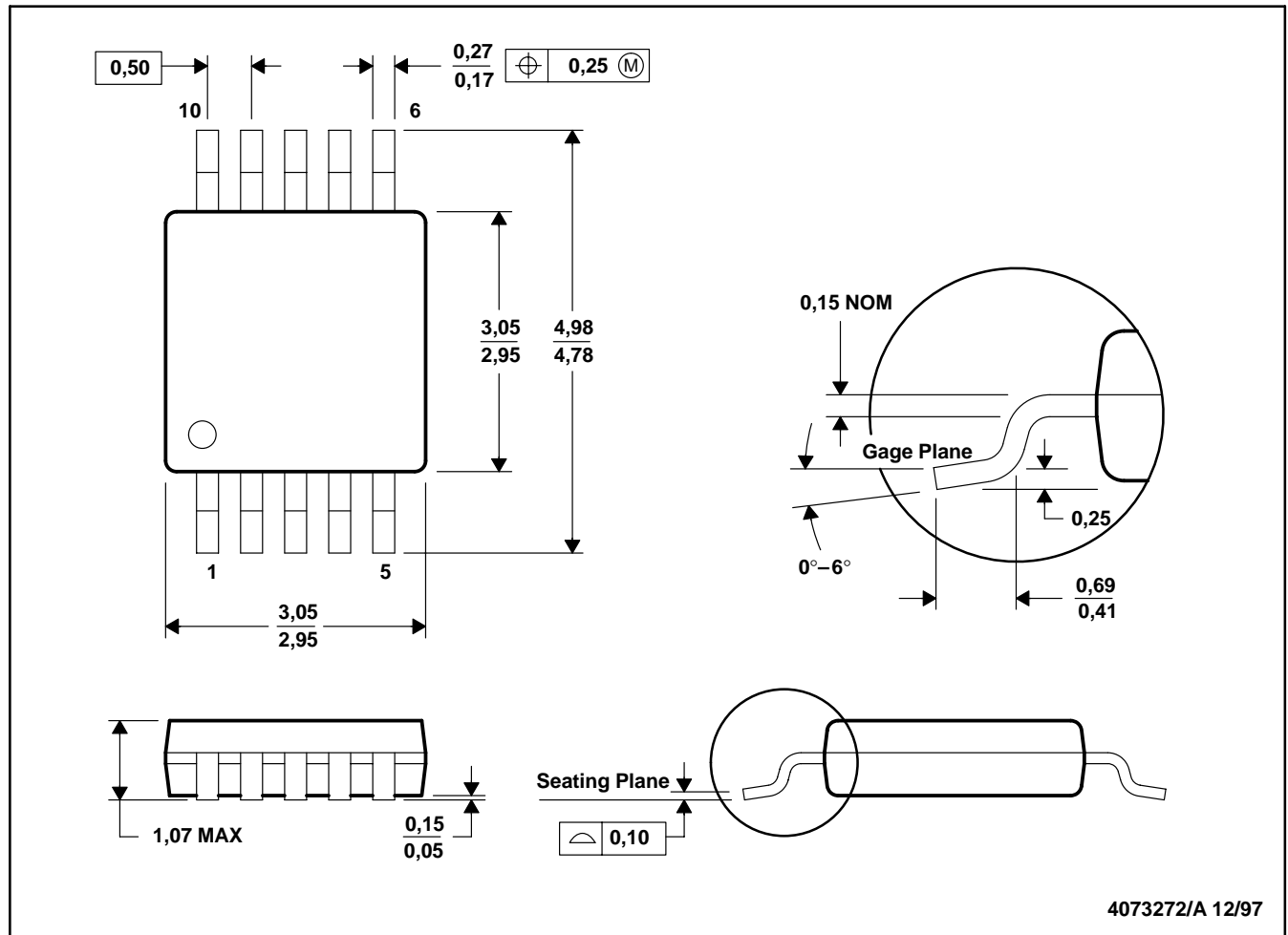
TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA  
 FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT  
 OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

MECHANICAL DATA

DGS (S-PDSO-G10)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion.

# TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA

## FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT

### OPERATIONAL AMPLIFIERS WITH SHUTDOWN

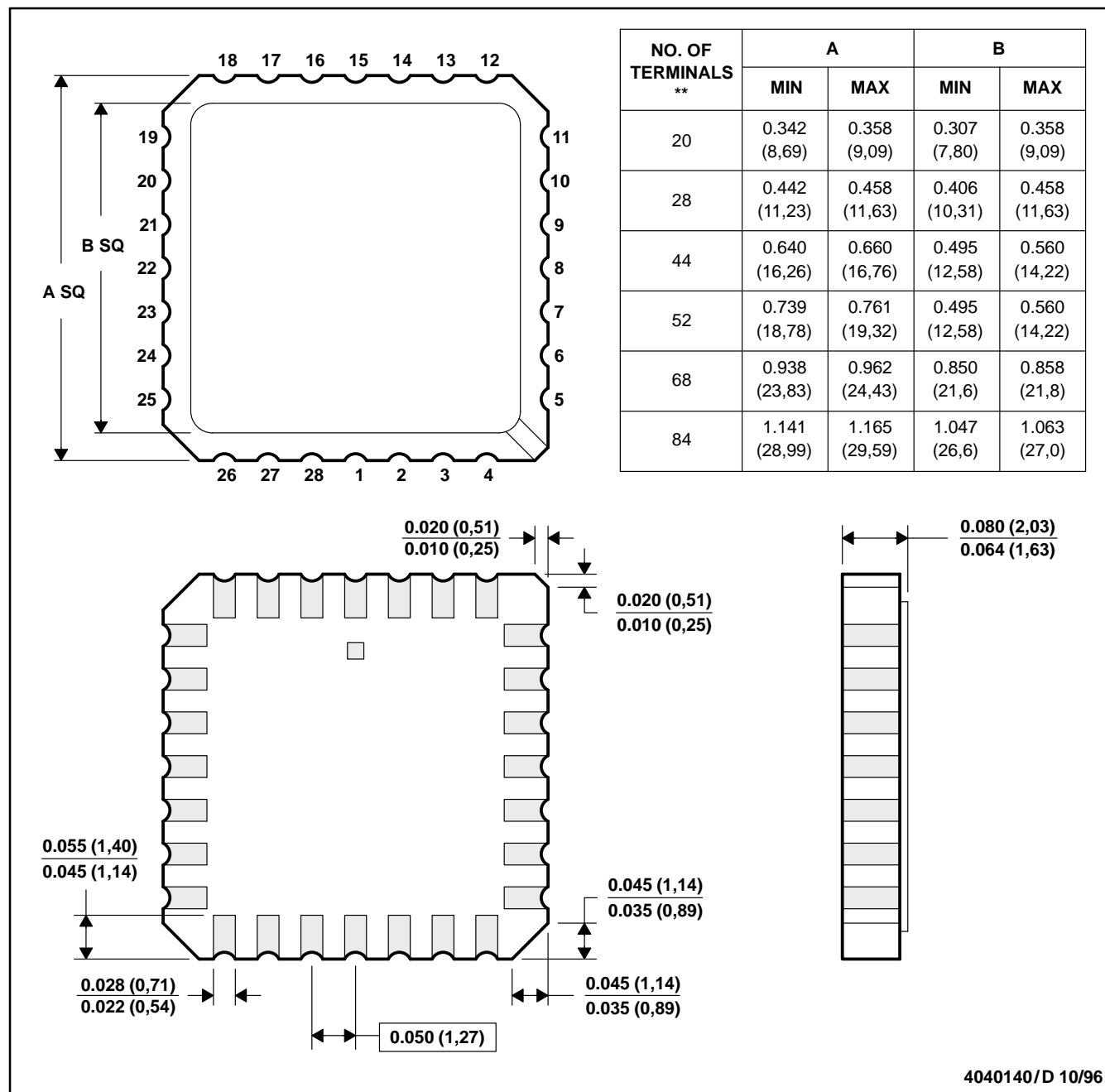
SLOS220I – JULY 1998 – REVISED MARCH 2001

#### MECHANICAL DATA

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004

**TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA**  
**FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT**  
**OPERATIONAL AMPLIFIERS WITH SHUTDOWN**

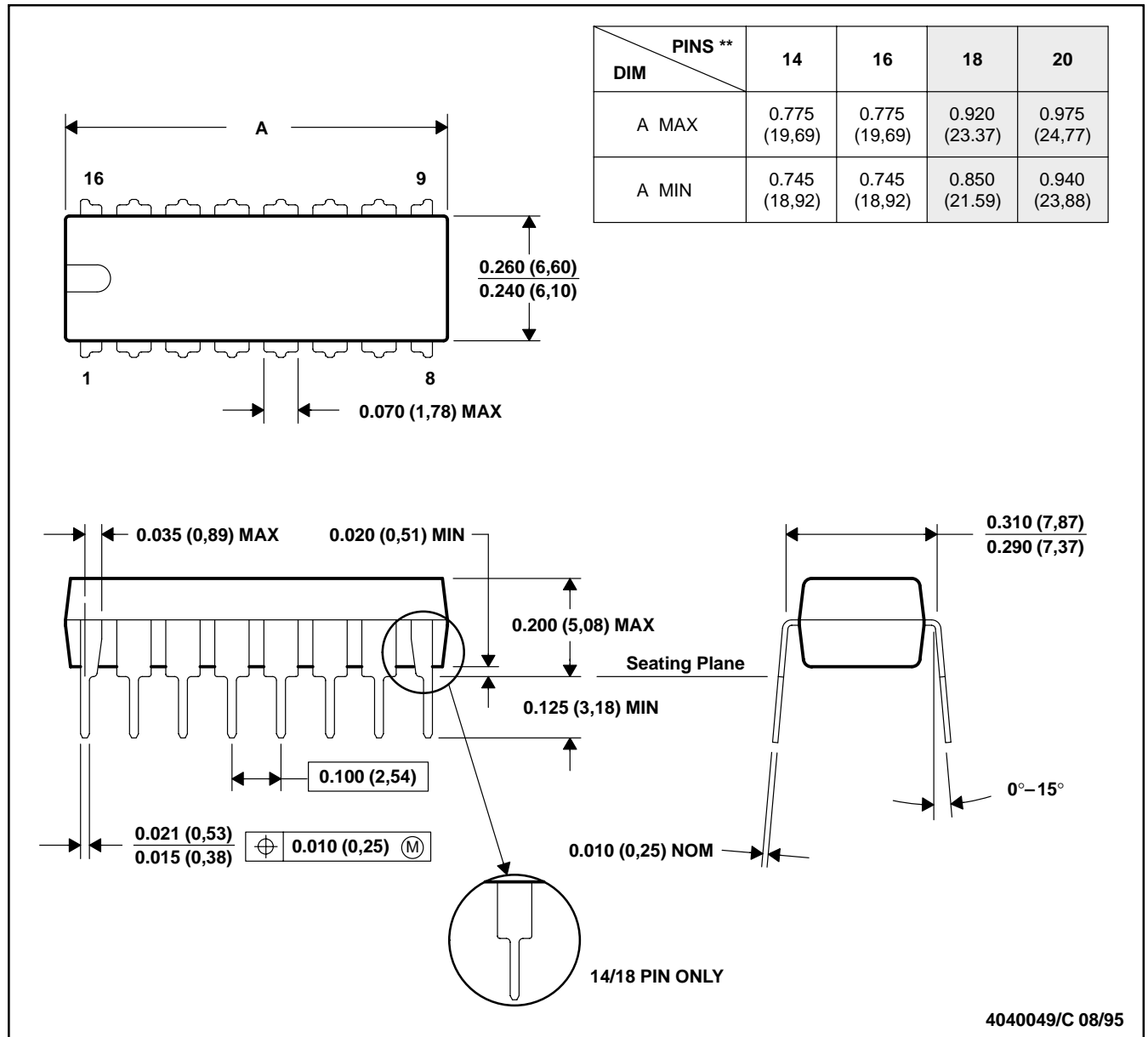
SLOS220I – JULY 1998 – REVISED MARCH 2001

**MECHANICAL DATA**

**N (R-PDIP-T\*\*)**

**PLASTIC DUAL-IN-LINE PACKAGE**

**16 PIN SHOWN**



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Falls within JEDEC MS-001 (20 pin package is shorter than MS-001.)

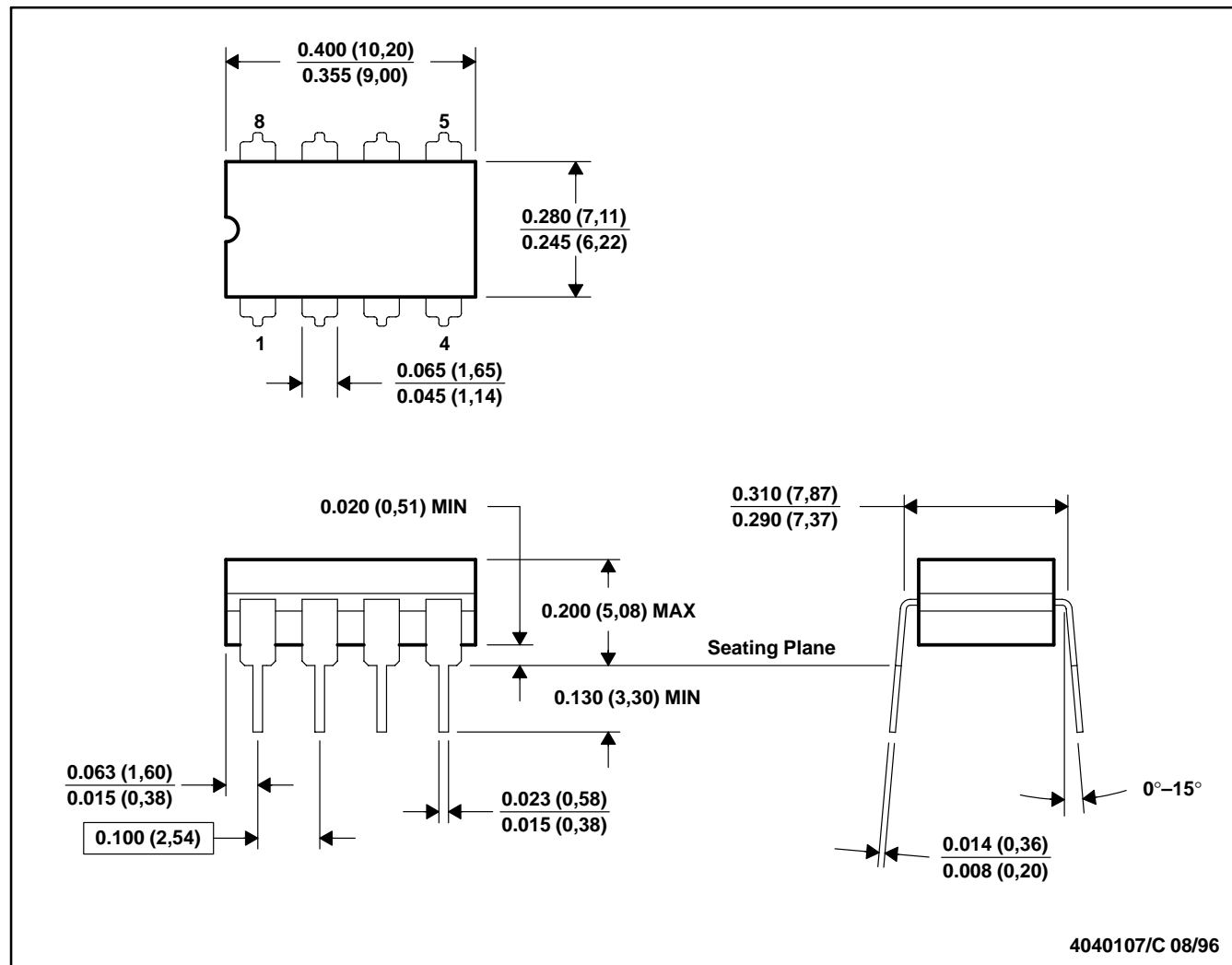
**TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA**  
**FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT**  
**OPERATIONAL AMPLIFIERS WITH SHUTDOWN**

SLOS220I – JULY 1998 – REVISED MARCH 2001

**MECHANICAL DATA**

**JG (R-GDIP-T8)**

**CERAMIC DUAL-IN-LINE PACKAGE**



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a ceramic lid using glass frit.  
 D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.  
 E. Falls within MIL-STD-1835 GDIP1-T8

**TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA**  
**FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT**  
**OPERATIONAL AMPLIFIERS WITH SHUTDOWN**

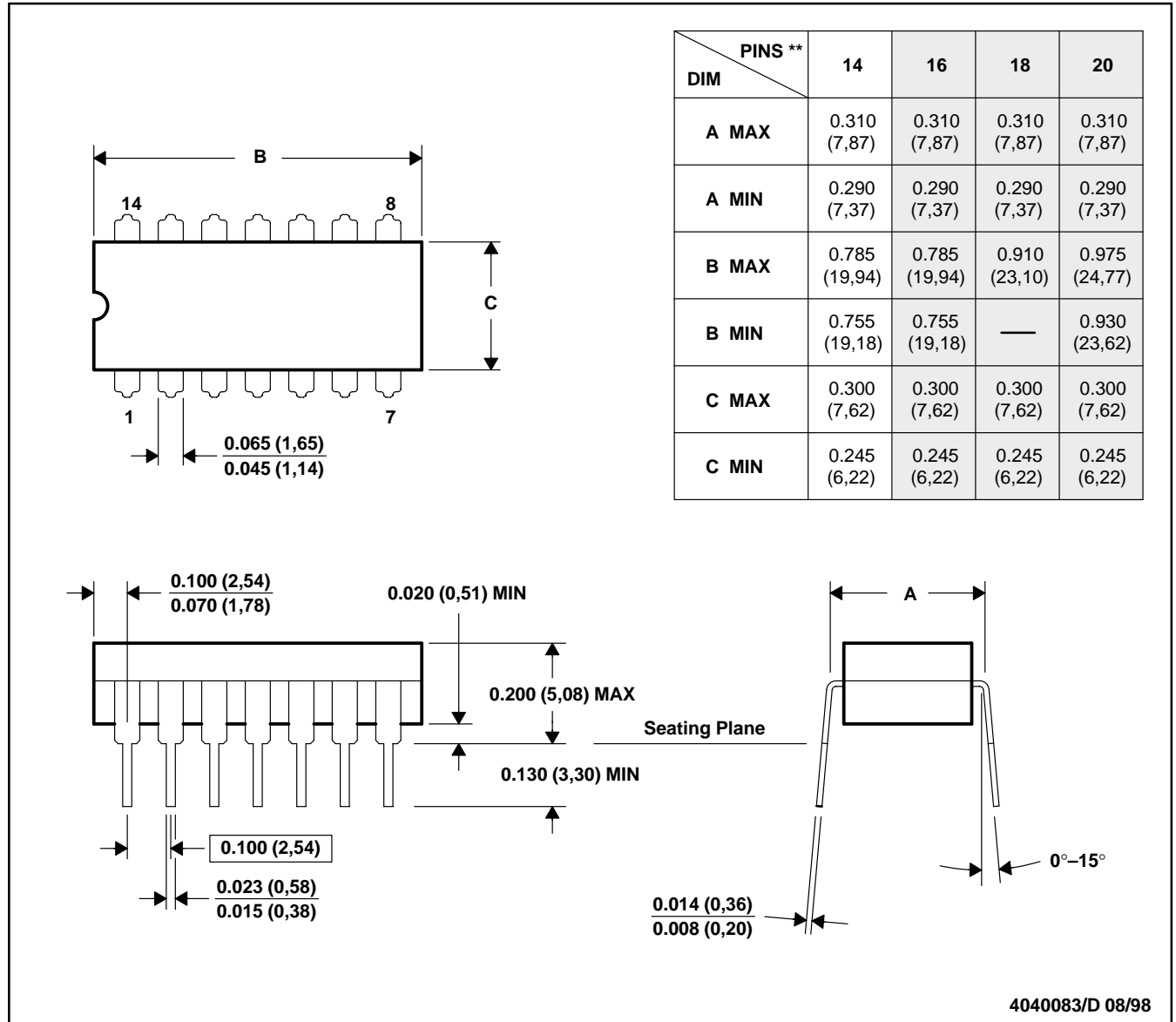
SLOS220I – JULY 1998 – REVISED MARCH 2001

**MECHANICAL DATA**

**J (R-GDIP-T\*\*)**

**CERAMIC DUAL-IN-LINE PACKAGE**

**14 PIN SHOWN**



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a ceramic lid using glass frit.  
 D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.  
 E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18, GDIP1-T20, and GDIP1-T22.

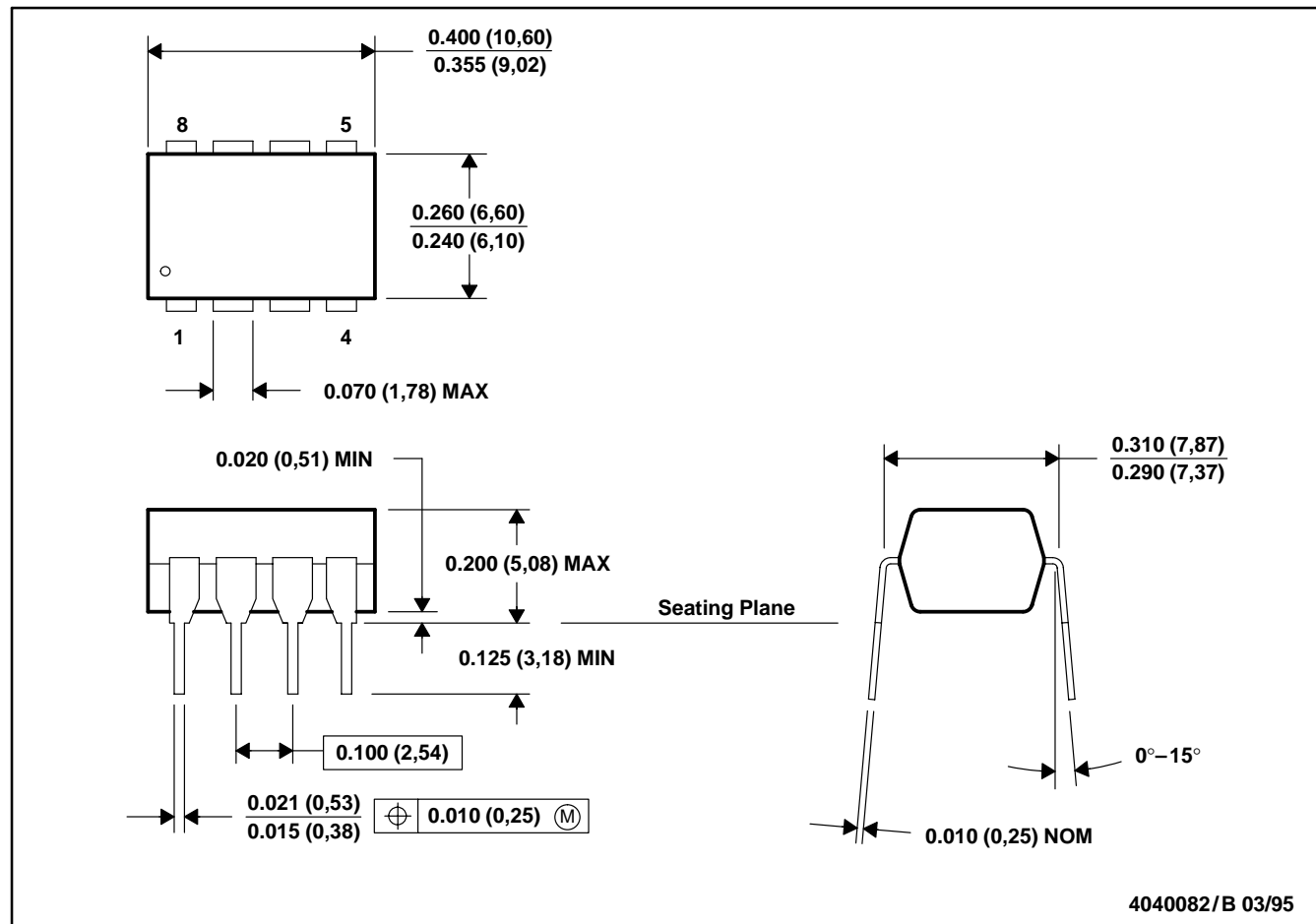
**TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA**  
**FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT**  
**OPERATIONAL AMPLIFIERS WITH SHUTDOWN**

SLOS220I – JULY 1998 – REVISED MARCH 2001

**MECHANICAL DATA**

**P (R-PDIP-T8)**

**PLASTIC DUAL-IN-LINE PACKAGE**



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Falls within JEDEC MS-001



**TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA**  
**FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT**  
**OPERATIONAL AMPLIFIERS WITH SHUTDOWN**

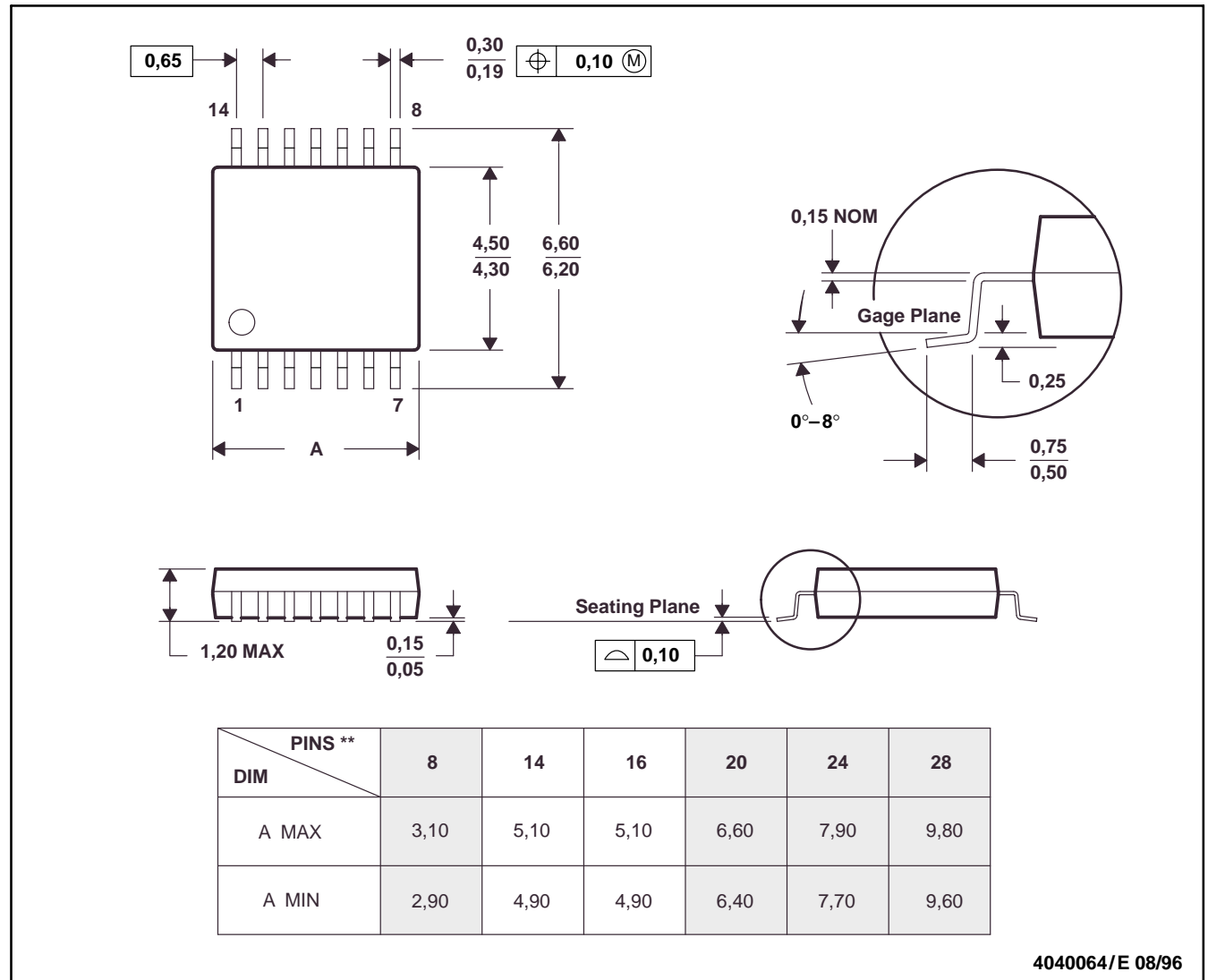
SLOS220I – JULY 1998 – REVISED MARCH 2001

## MECHANICAL DATA

**PW (R-PDSO-G\*\*)**

**PLASTIC SMALL-OUTLINE PACKAGE**

**14 PIN SHOWN**



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

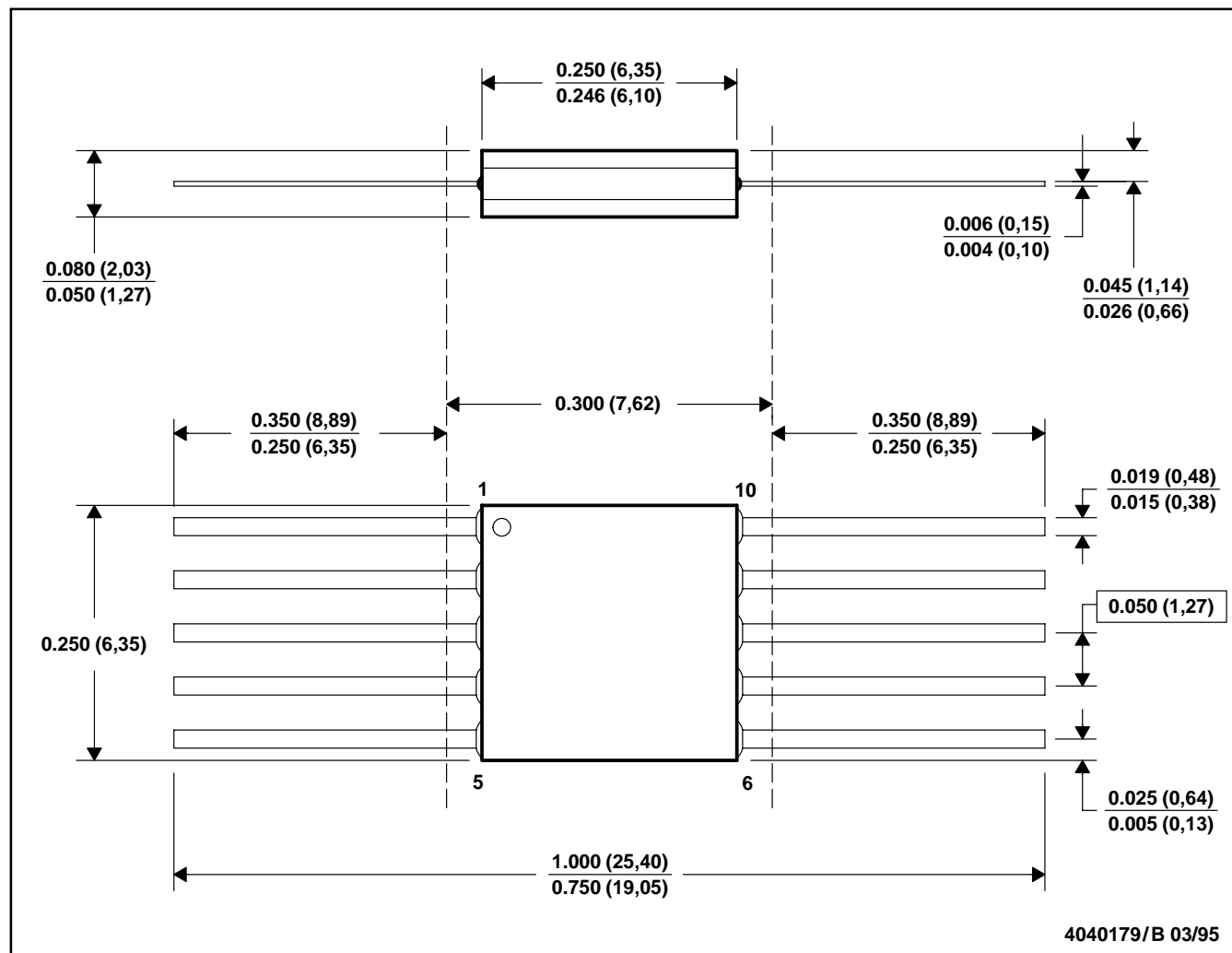
**TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA**  
**FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT**  
**OPERATIONAL AMPLIFIERS WITH SHUTDOWN**

SLOS220I – JULY 1998 – REVISED MARCH 2001

**MECHANICAL DATA**

**U (S-GDFP-F10)**

**CERAMIC DUAL FLATPACK**



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a ceramic lid using glass frit.  
 D. Index point is provided on cap for terminal identification only.  
 E. Falls within MIL STD 1835 GDFP1-F10 and JEDEC MO-092AA

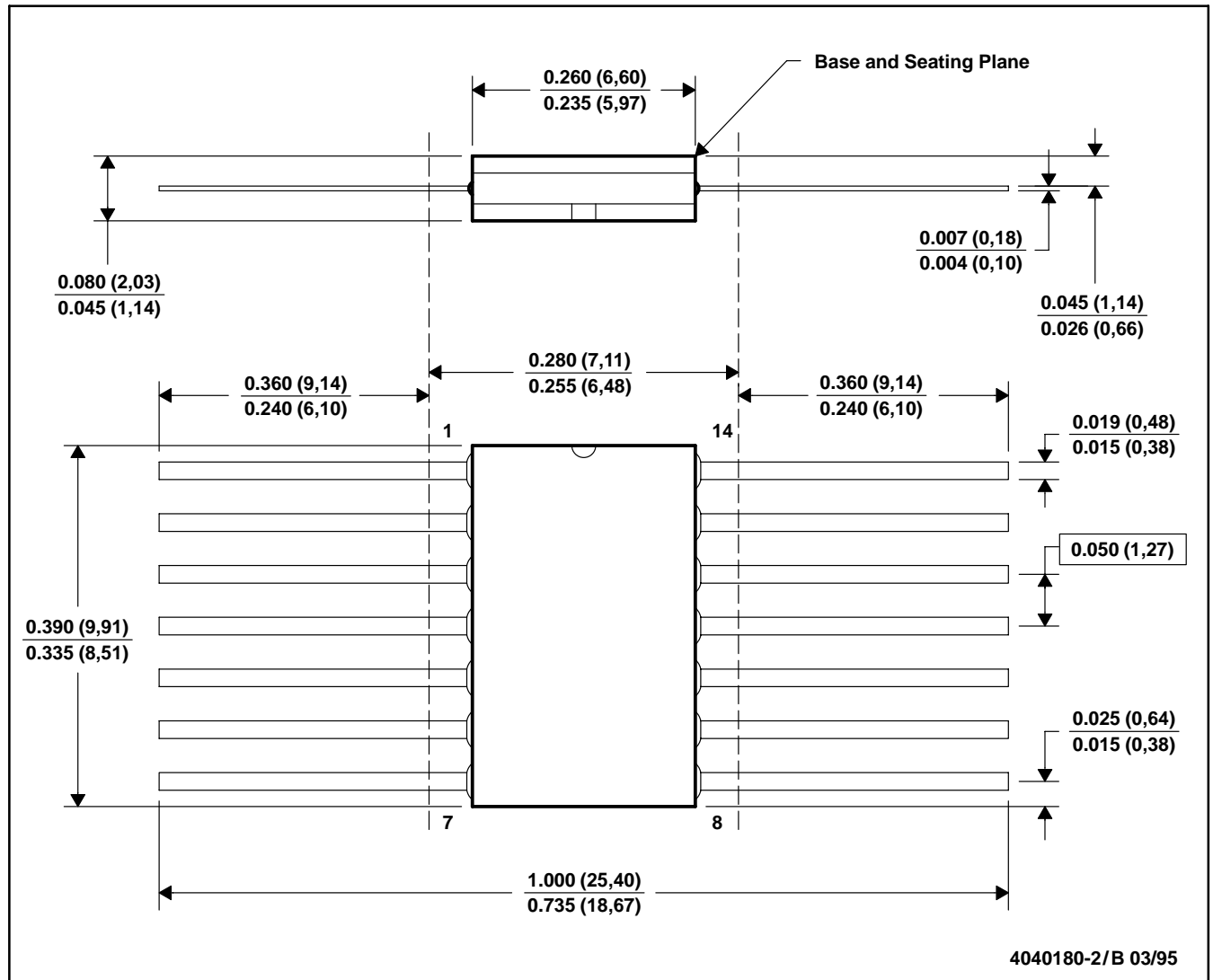
TLV2460, TLV2461, TLV2462, TLV2463, TLV2464, TLV2465, TLV246xA  
FAMILY OF LOW-POWER RAIL-TO-RAIL INPUT/OUTPUT  
OPERATIONAL AMPLIFIERS WITH SHUTDOWN

SLOS220I – JULY 1998 – REVISED MARCH 2001

MECHANICAL INFORMATION

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

## JG (R-GDIP-T8)

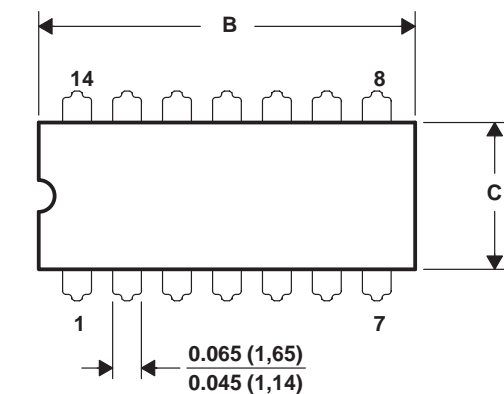
## CERAMIC DUAL-IN-LINE



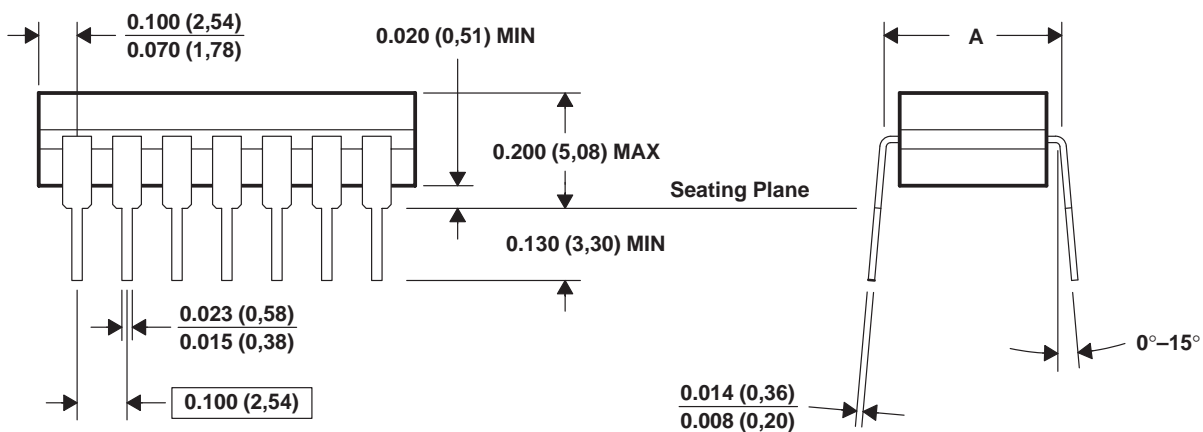
- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification.
  - E. Falls within MIL STD 1835 GDIP1-T8

## CERAMIC DUAL-IN-LINE

14 LEADS SHOWN



<b>PINS **</b> <b>DIM</b>	<b>14</b>	<b>16</b>	<b>20</b>
<b>A MAX</b>	0.310 (7,87)	0.310 (7,87)	0.310 (7,87)
<b>A MIN</b>	0.290 (7,37)	0.290 (7,37)	0.290 (7,37)
<b>B MAX</b>	0.785 (19,94)	0.785 (19,94)	0.975 (24,77)
<b>B MIN</b>	0.755 (19,18)	0.755 (19,18)	0.930 (23,62)
<b>C MAX</b>	0.300 (7,62)	0.300 (7,62)	0.300 (7,62)
<b>C MIN</b>	0.245 (6,22)	0.245 (6,22)	0.245 (6,22)

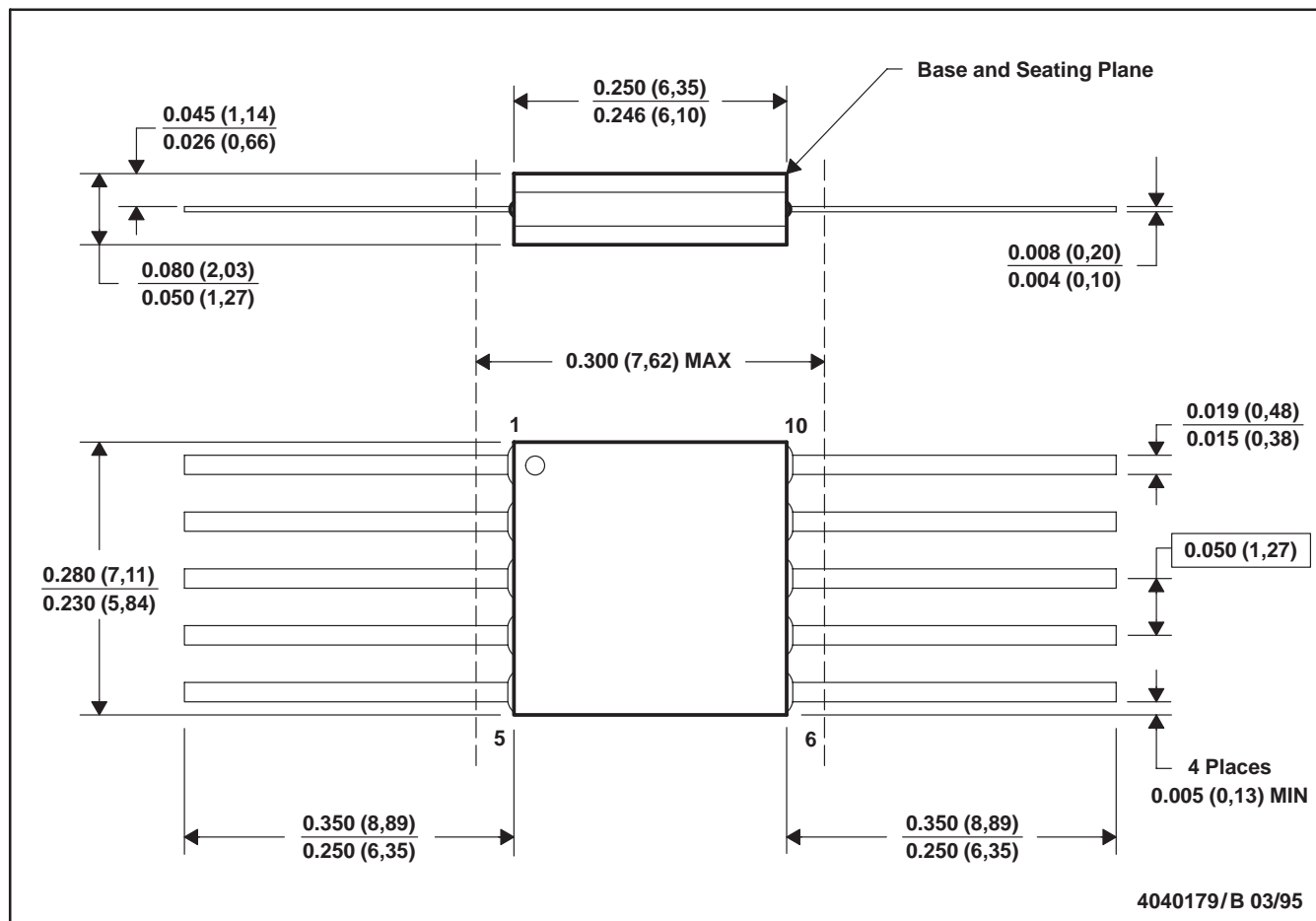


4040083/E 03/99

- NOTES: A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.  
C. This package is hermetically sealed with a ceramic lid using glass frit.  
D. Index point is provided on cap for terminal identification.  
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, and GDIP1-T20

## U (S-GDFP-F10)

## CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a ceramic lid using glass frit.  
 D. Index point is provided on cap for terminal identification only.  
 E. Falls within MIL STD 1835 GDFP1-F10 and JEDEC MO-092AA

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

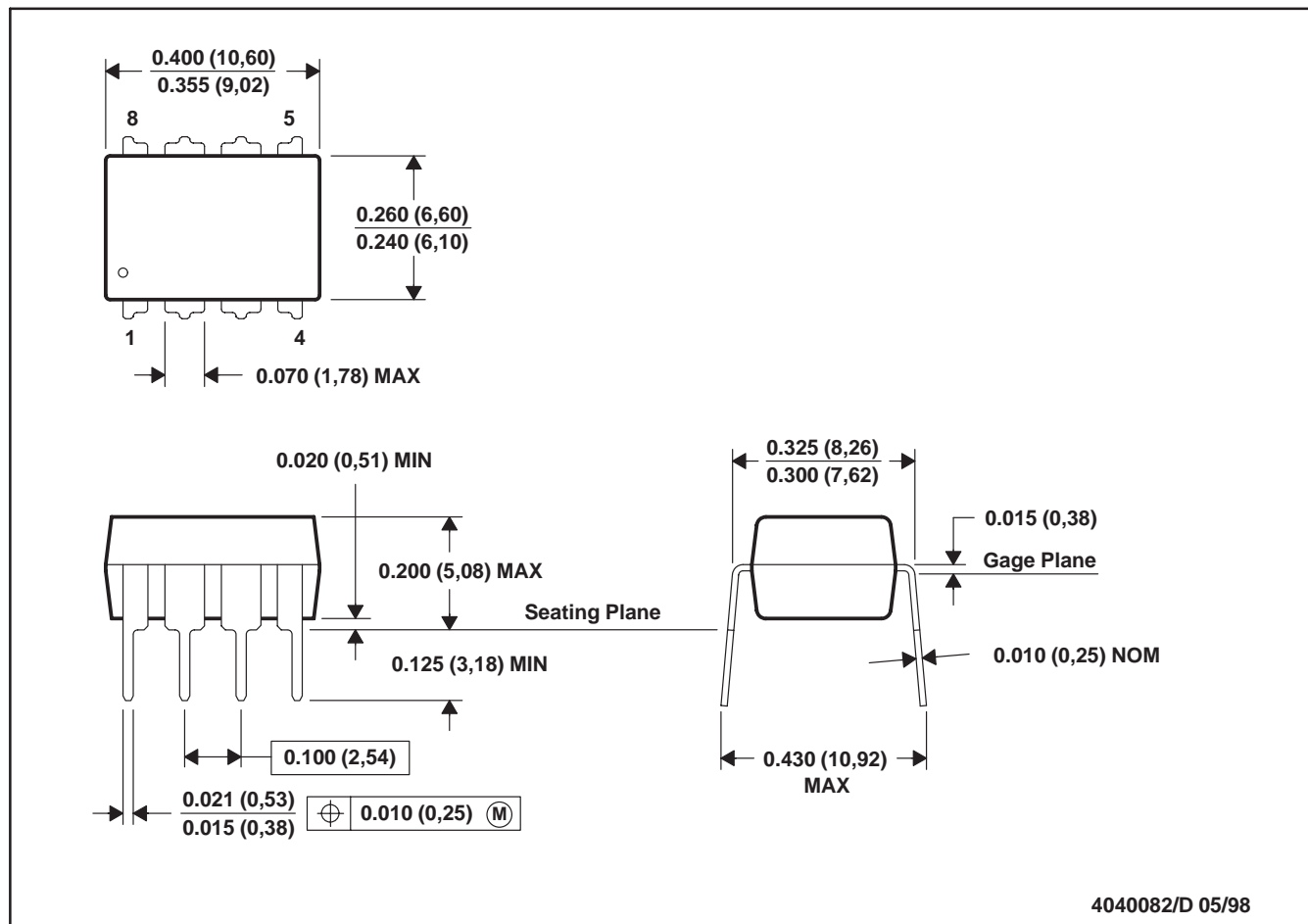
28 TERMINAL SHOWN



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - The terminals are gold plated.
  - Falls within JEDEC MS-004

## P (R-PDIP-T8)

## PLASTIC DUAL-IN-LINE



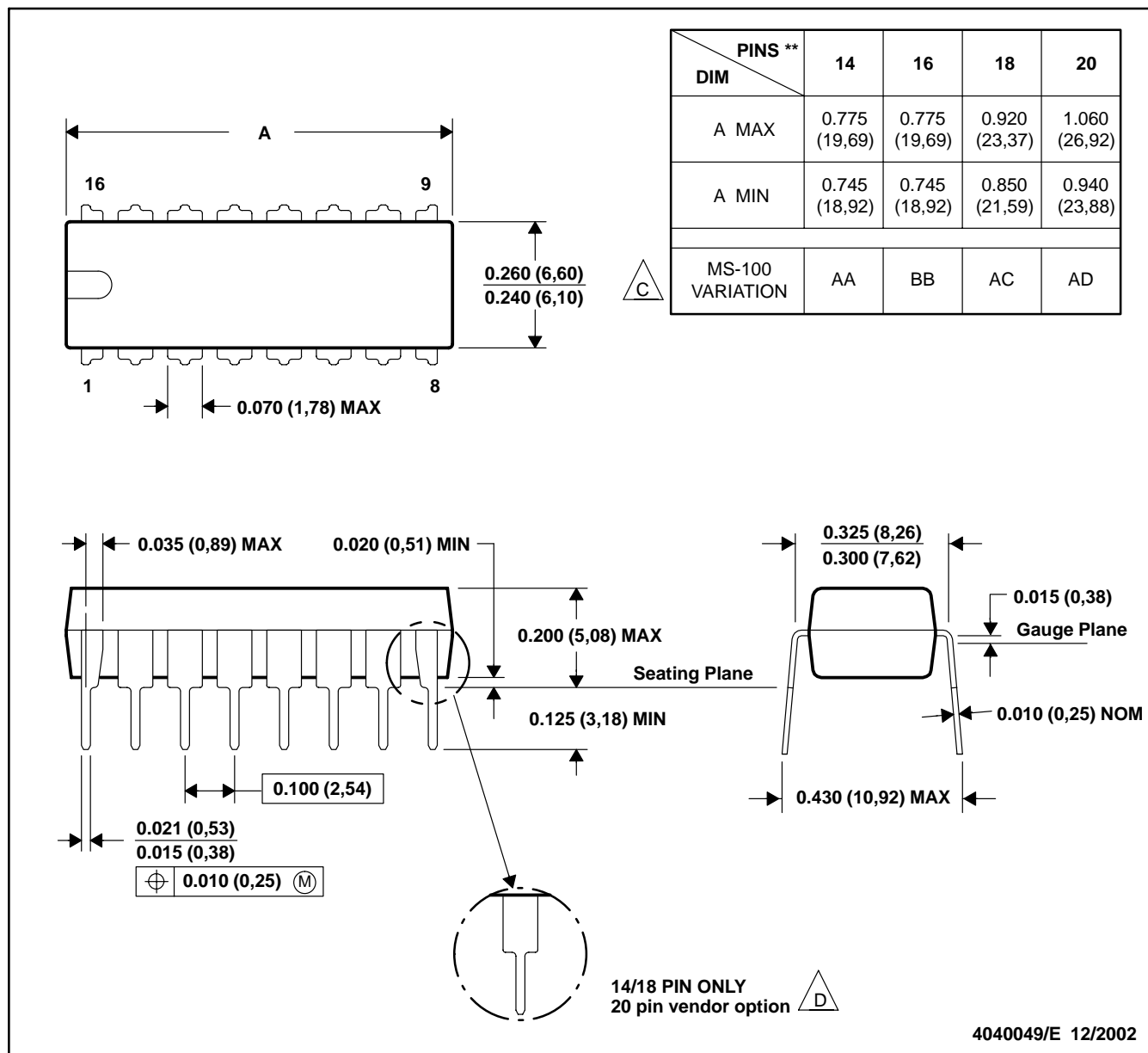
NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Falls within JEDEC MS-001

For the latest package information, go to [http://www.ti.com/sc/docs/package/pkg\\_info.htm](http://www.ti.com/sc/docs/package/pkg_info.htm)



**N (R-PDIP-T\*\*)**

16 PINS SHOWN

**PLASTIC DUAL-IN-LINE PACKAGE**

NOTES: A. All linear dimensions are in inches (millimeters).

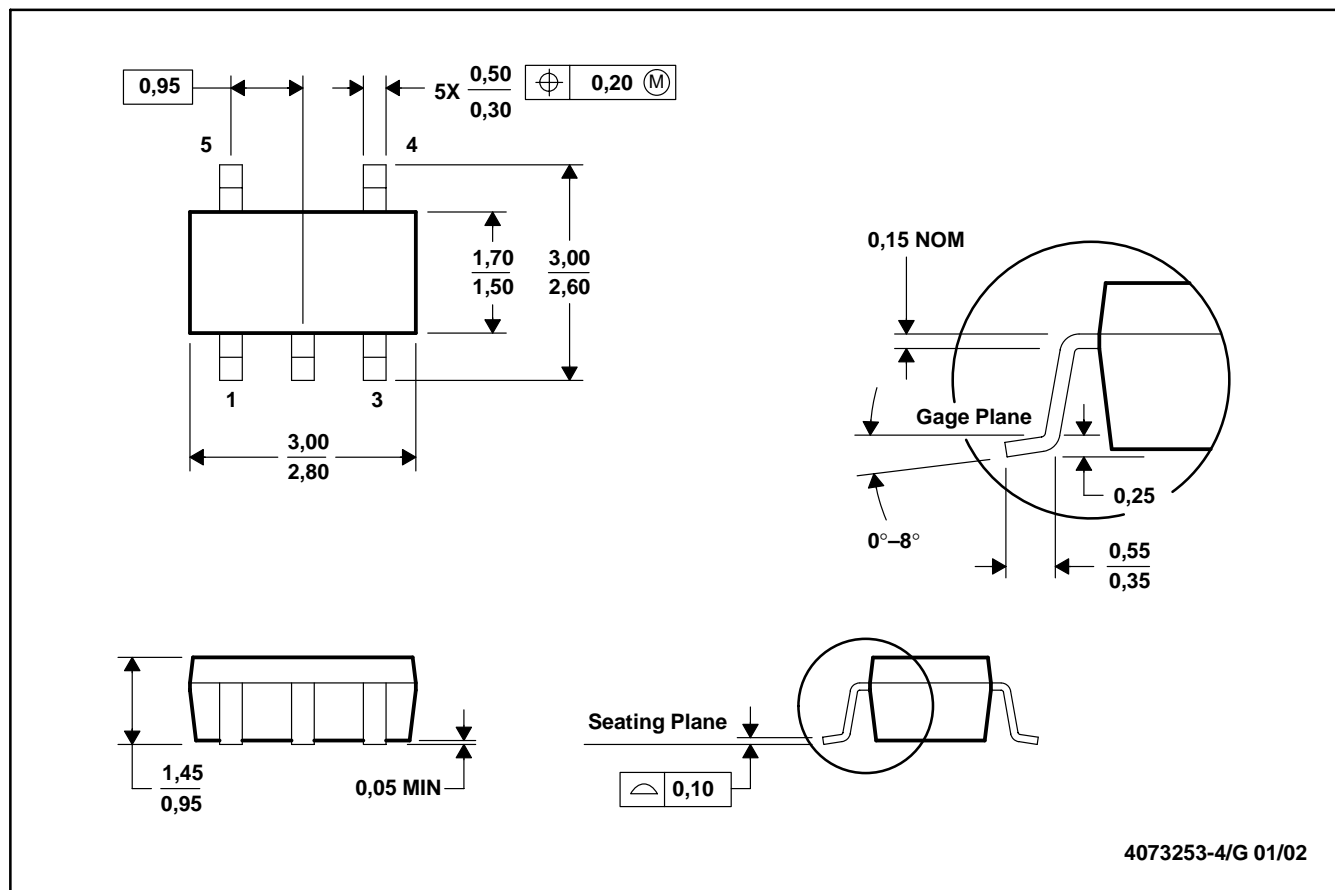
B. This drawing is subject to change without notice.

C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

D The 20 pin end lead shoulder width is a vendor option, either half or full width.

## DBV (R-PDSO-G5)

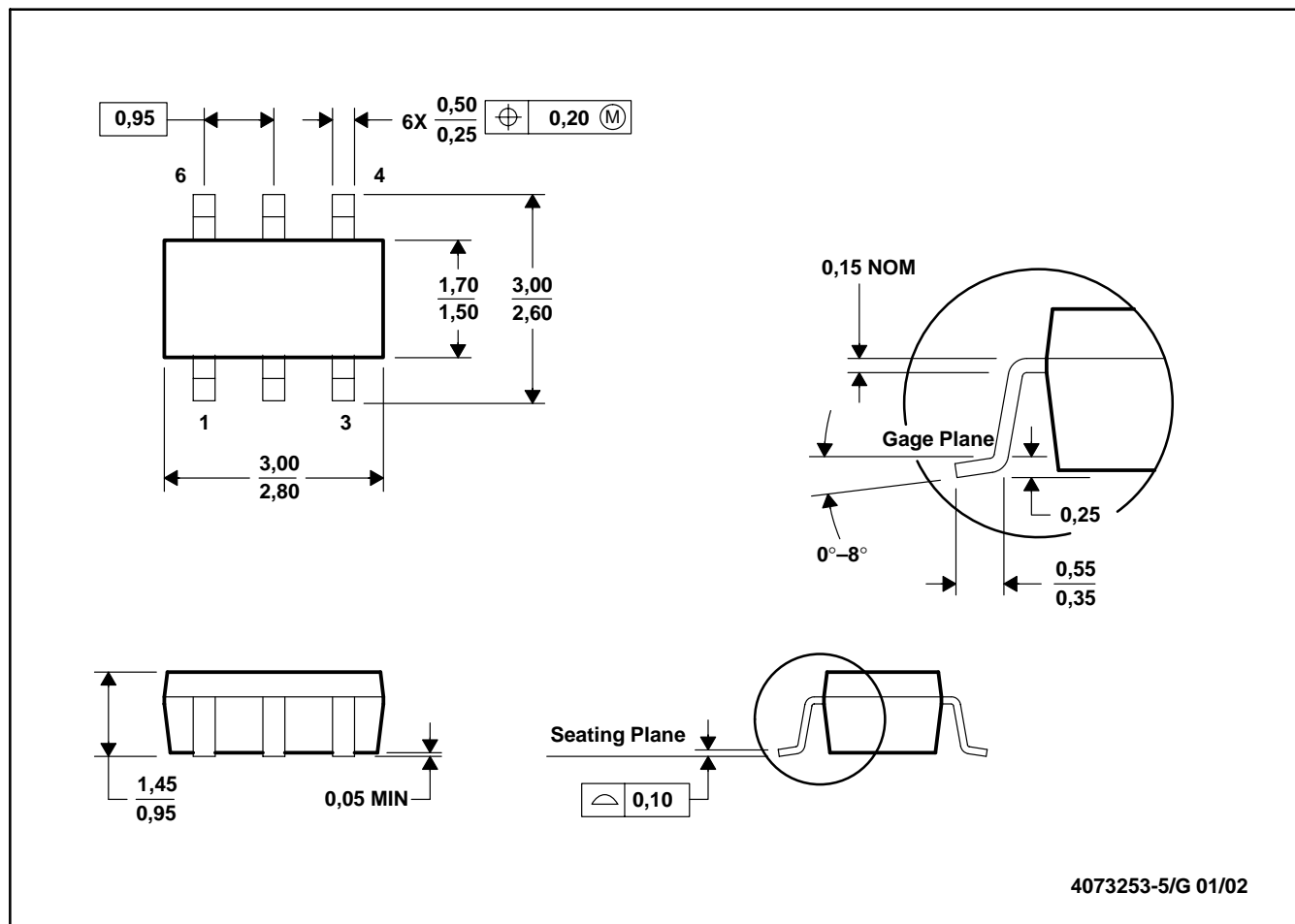
## PLASTIC SMALL-OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion.
  - Falls within JEDEC MO-178

DBV (R-PDSO-G6)

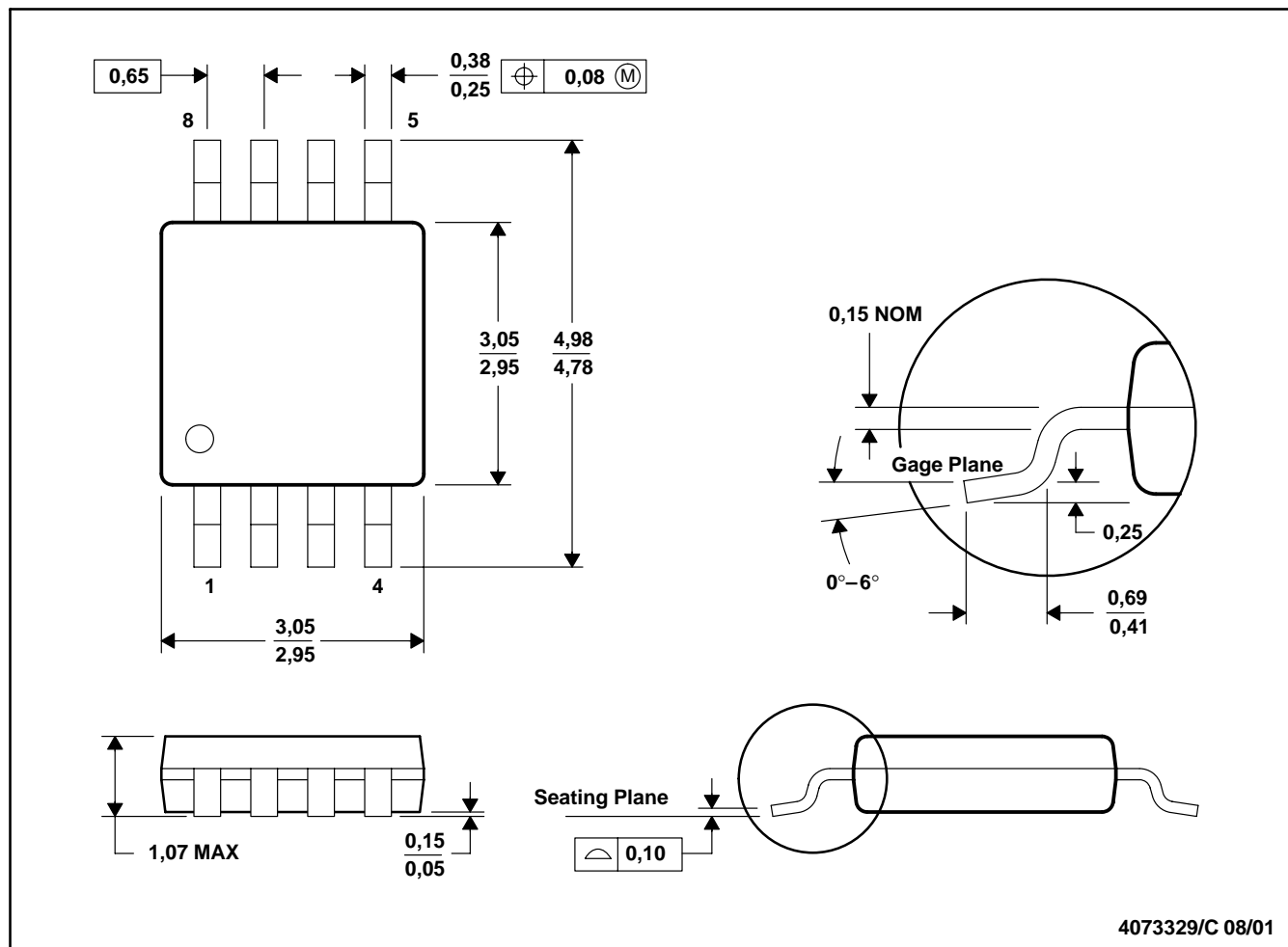
PLASTIC SMALL-OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion.
  - D. Leads 1, 2, 3 may be wider than leads 4, 5, 6 for package orientation.

## DGK (R-PDSO-G8)

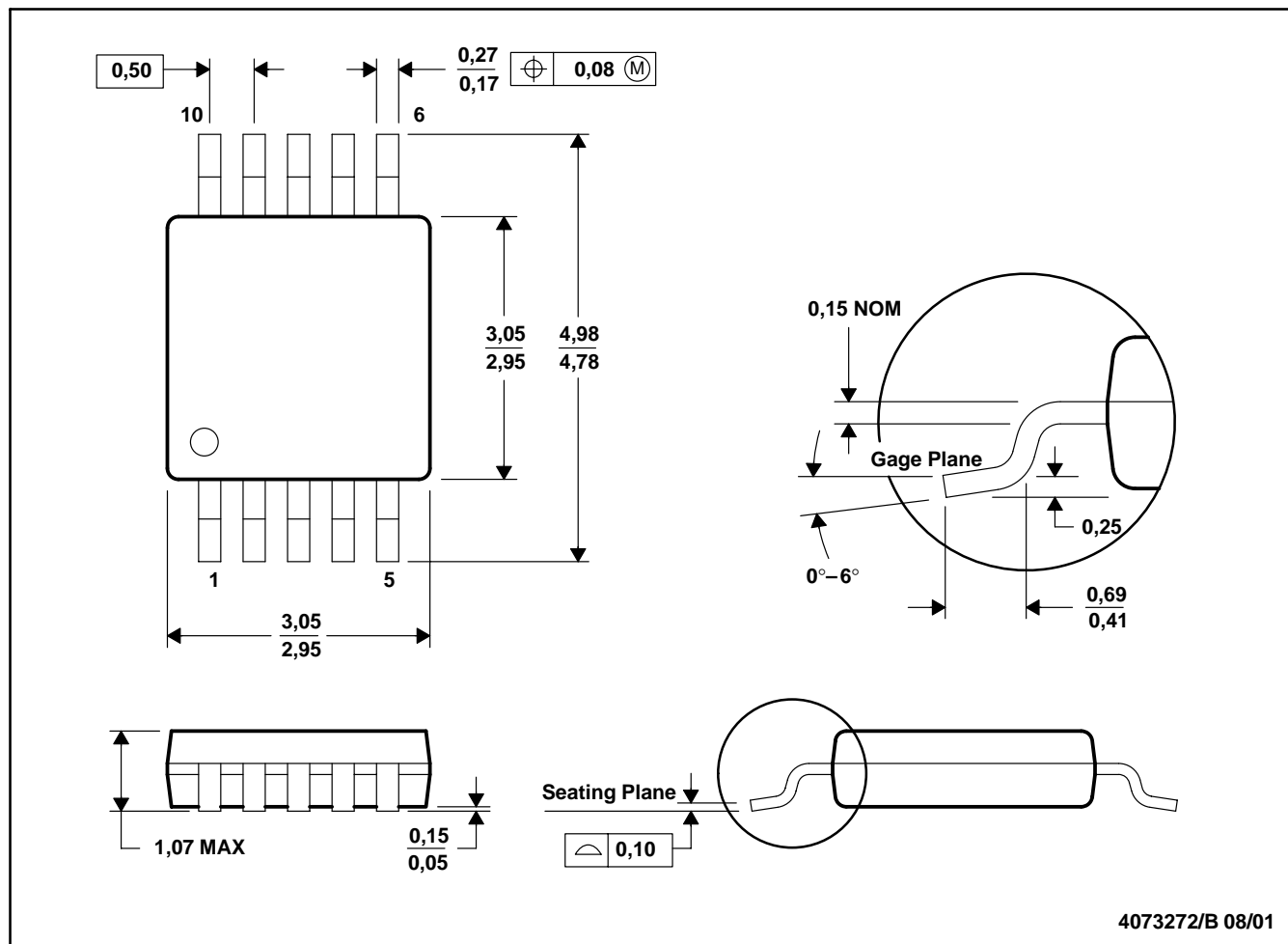
## PLASTIC SMALL-OUTLINE PACKAGE



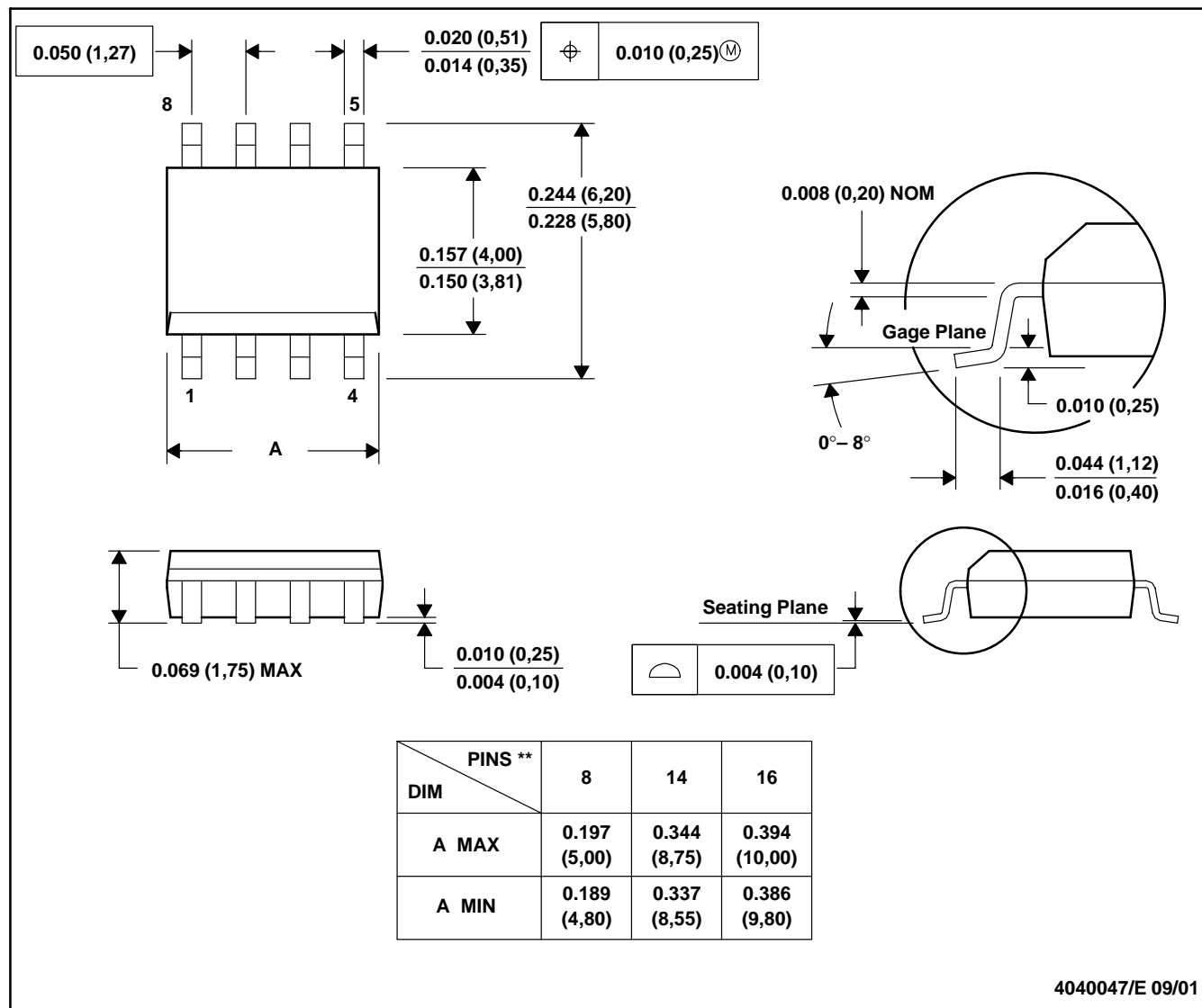
- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion.
  - Falls within JEDEC MO-187

## DGS (S-PDSO-G10)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion.  
 D. Falls within JEDEC MO-187

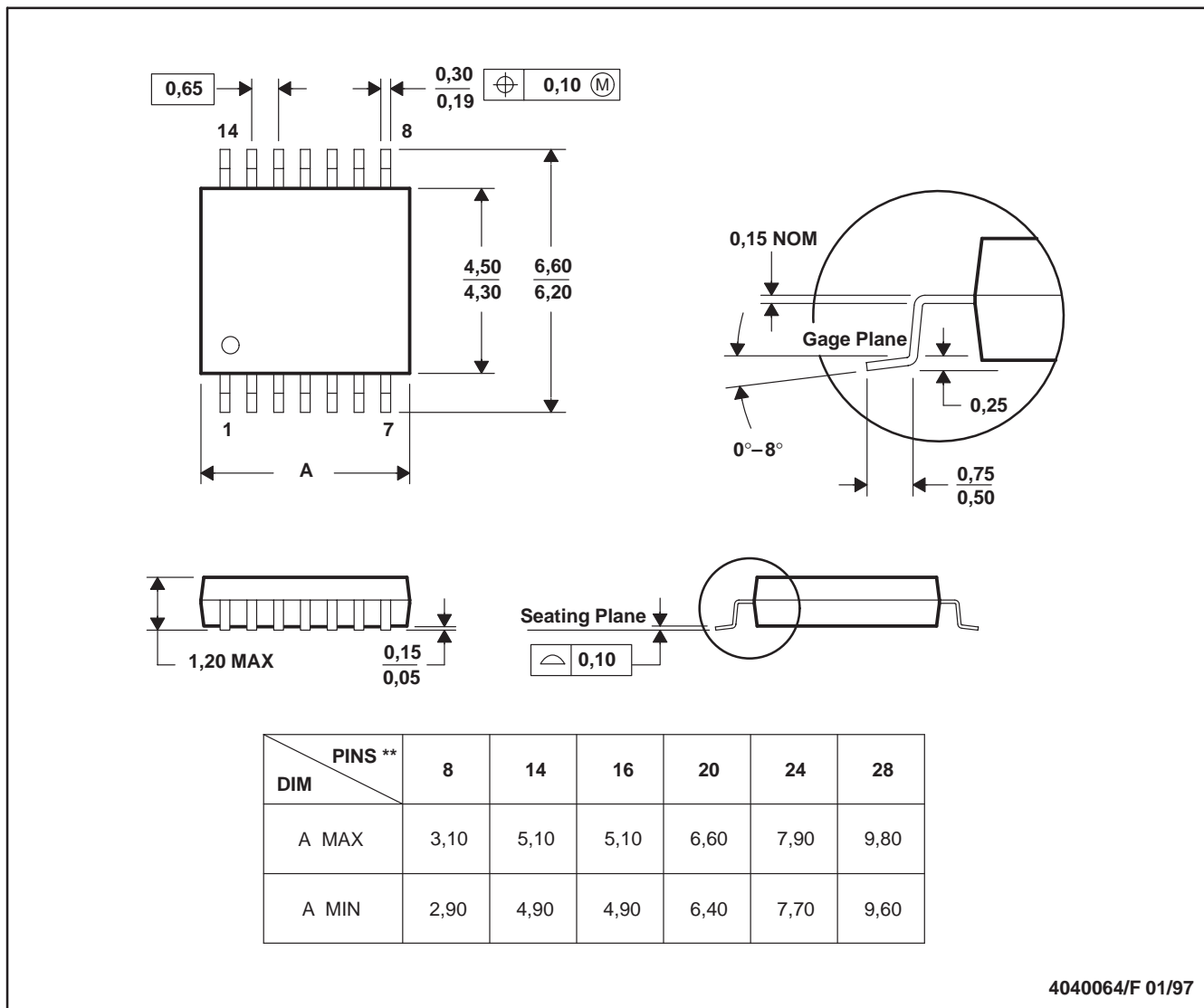
**D (R-PDSO-G\*\*)****PLASTIC SMALL-OUTLINE PACKAGE****8 PINS SHOWN**

- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).  
 D. Falls within JEDEC MS-012

## PW (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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